
RZ/N2H Group

Modbus RTU/ASCII Software

Introduction

This document explains the evaluation of Modbus communication using the RZ microcomputer evaluation board. Modbus protocol is a communication protocol developed by Modicon Inc. (Schneider Electric SA.) for programmable logic controllers (PLCs), and its specifications are open to the public.

For details, refer to the protocol specifications (PI-MBUS-300 Rev.J).

Target Device

RZ/N2H

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1. Overview

This document is for the Modbus protocol stack that operates on the RZ/N2H board, and describes the function overview, application programming interface (API), and application samples for developing and implementing applications using the protocol stack. Among the multiple cores installed, we will describe examples using Cortex®-R52 and Cortex®-A55.

This package supports the RS-485 based Modbus RTU/ASCII protocol.

1.1 Abbreviations / Definitions

Table 1.1 Abbreviations/Definitions

Index	Abbreviations / Definitions	Description
1	IP	Internet Protocol
2	TCP	Transmission Control Protocol
3	USB	Universal Serial Bus
4	PC	Personal Computer
5	SW	Switch
6	EWARM	Embedded Workbench® for Arm
7	LED	Light Emitting Diode
8	Wireshark	A free packet capture tool for monitoring LAN traffic
9	Client	Modbus TCP Master / Requesting device
10	Server	Modbus TCP Slave / Responding device
11	MAC	Media Access Control Address
12	LAN	Local Area Network
13	DHCP	Dynamic Host Configuration Protocol
14	PHY	Physical Layer
15	lwIP	Lightweight IP
16	RS485	EIA-485 / Serial communication standard
17	SBOM	Software Bill of Materials

1.2 Reference

Technical information regarding Modbus can be found on the official Modbus Organization website, while details on the RZ/N2H are provided by Renesas.

Table 1.2 Technical References for RZ/N2H

Document Type	Document Title	Description	Document No.
User's Manual	RZ/T2H and RZ/N2H Group User's Manual Hardware	RZ/T2H and RZ/N2H Group User's Manual Hardware	r01uh1039ej****
Datasheet	RZ/T2H and RZ/N2H Group Datasheet	RZ/T2H and RZ/N2H Group Datasheet	r01ds0426ej****
Getting Started	RZ/T2, RZ/N2 Group FSP Getting Started Guide	RZ/T2, RZ/N2 Group Flexible Software Package Getting Started Guide	r01an6434ej****
User's Manual	RZ/N2H Evaluation Board User's Manual	RZ/N2H Evaluation Board User's Manual	r20ut5522ej****
Reference Guide	Modicon Modbus Protocol Reference Guide Rev.J	Modbus Protocol Reference Guide Rev.J	PI-MBUS-300 Rev. J
Specification	Modbus Application Protocol Specification V1.1b3	Modbus Application Protocol Specification V1.1b3	v1.1b3

2. Features

The Modbus protocol stack for RZ/N2H allows for quick and easy development of the Modbus RTU/ASCII applications. The following nine Modbus function codes are supported by this stack.

1. (0x01) - Read coils
2. (0x02) - Read discrete input
3. (0x03) - Read holding registers
4. (0x04) - Read input registers
5. (0x05) - Write single coil
6. (0x06) - Write single register
7. (0x0F) - Write multiple coils
8. (0x10) - Write multiple registers
9. (0x17) - Read/Write multiple registers

For more information about Modbus, refer to the following site:

<http://www.modbus.org>

Note: The version number may differ depending on the update. Refer to the latest manual.

3. Requirements (Software and Hardware)

This project was developed and tested in the environment listed below using the following boards and tools.

3.1 Requirements for this sample package

Table 3.1 Requirements

Category	Name	Version	Description
Board	RZ/N2H Evaluation Board	-	RZ/N2H Evaluation Board Renesas Evaluation Board Kit for RZ/N2H
IDE	Flexible Software Package	V4.1.0	Renesas Flexible Software Package (FSP)
	e ² studio	2026-04.1	
	- GNU ARM Embedded Toolchain	13.3.1.arm-13-24 for CR52	
	- GNU ARM A-Profile (AArch64 bare-metal)	13.2.1.20231009 for CA55	
	IAR Systems	9.60.3	
	- Embedded Workbench for ARM	EWARM_Patch_f or_RZT2H_N2H_rev1.0	
	- patch		
	GNU ARM Embedded Toolchain	13.3.1.arm-13-24 for CR52	
	GNU ARM A-Profile (AArch64 bare-metal)	13.2.1.20231009 for CA55	
Emulator	J-Link TM	8.60	SEGGER SEGGER - The Embedded Experts - Downloads - J-Link / J-Trace
Software	ModbusDemoApplication.exe	V1.3	

3.2 Hardware

This document describes the major hardware. Refer to Renesas Starter Kit+ for RZ/N2H user's manual and schematic for more board details.

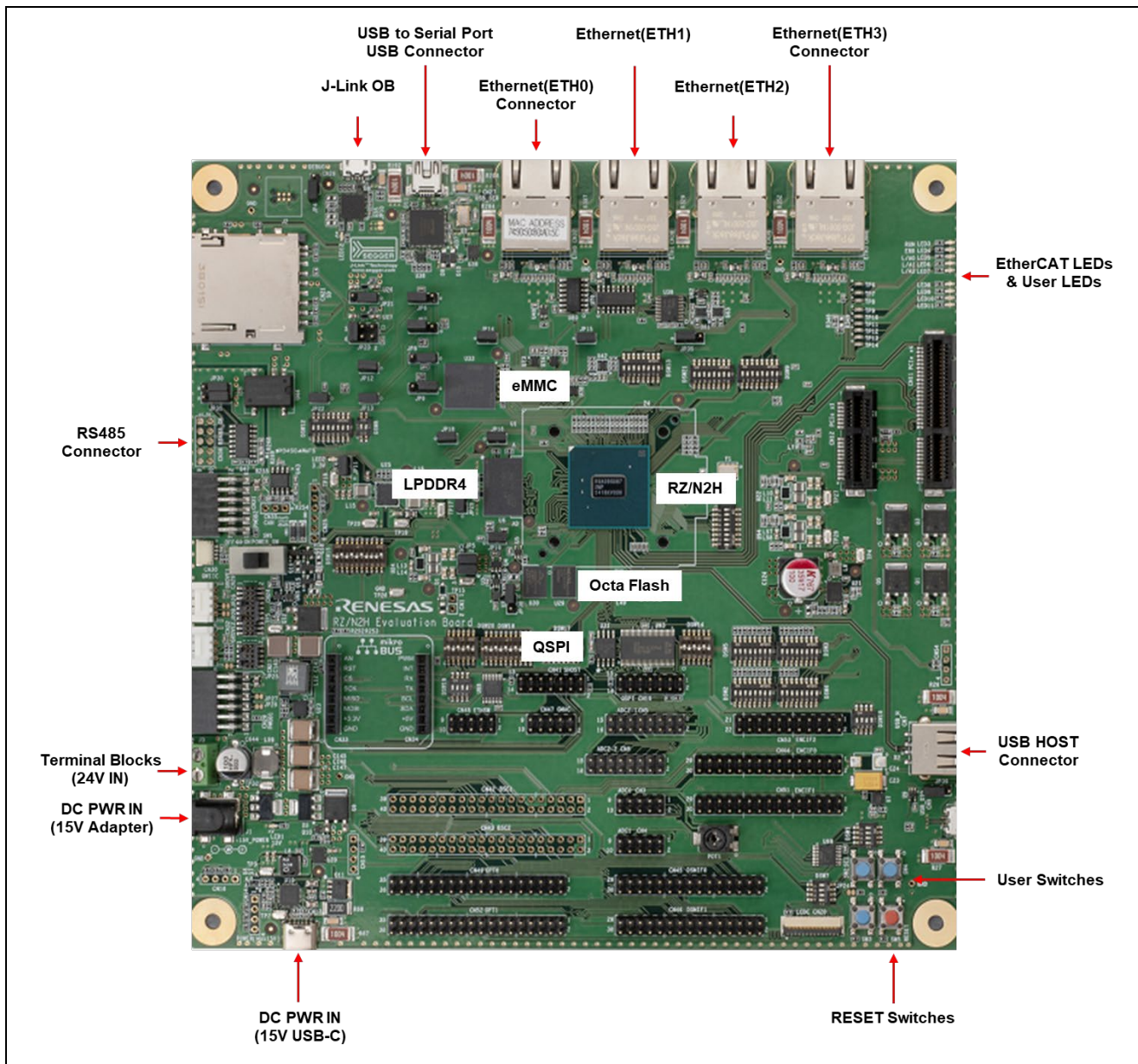


Figure 3.1 RZ/N2H Evaluation board layout.

Table 3.2 Jumper Pin settings (Power Selection)

Reference	Jumper Position	Description
JP6	Short 1-2	1.8-V power is supplied to VCC1833_0. (for Ethernet Port 0)
	Short 2-3	3.3-V power is supplied to VCC1833_0. (for Ethernet Port 0)
JP7	Short 1-2	1.8-V power is supplied to VCC1833_1. (for Ethernet Port 1)
	Short 2-3	3.3-V power is supplied to VCC1833_1. (for Ethernet Port 1)
JP8	Short 1-2	1.8-V power is supplied to VCC1833_1. (for Ethernet Port 2)
	Short 2-3	3.3-V power is supplied to VCC1833_1. (for Ethernet Port 2)
JP9	Short 1-2	1.8-V power is supplied to VCC1833_1. (for Ethernet Port 3)
	Short 2-3	3.3-V power is supplied to VCC1833_1. (for Ethernet Port 3)
JP21	Short 1-2	3.3-V power is supplied to VCC1833_7. (for SD1)
	Short 2-3	Power control IC output for SD1 is supplied to VCC1833_7. (for SD1)
JP23	Short 1-2	3.3-V power is supplied to VCC1833_6. (for SD0)
	Short 2-3	The output from the power-supply control IC for SD0 is supplied to VCC1833_6 (for SD0).
	Short 5-6	1.8-V power is supplied to VCC1833_6. (for SD0)
JP35	Short 1-2	VCC1833_0 is supplied to VCC_ETH2_MDIO (DSW5-6 is ON: When P21_4 and P21_5 are selected for MDIO).
	Short 2-3	VCC1833_2 is supplied to VCC_ETH2_MDIO. (DSW5-6 is OFF: When P30_5 and P30_6 are selected for MDIO)

Table 3.3 Jumper Pin settings (Debugging Function)

Reference	Jumper Position	Description
JP40	Open - circuit	The on-board debugging function J-Link® OB is enabled.
	Short-circuit	The on-board debugging function J-Link™ OB is disabled. Connect an external emulator to CN23 or CN24 at debugging.

Table 3.4 Jumper Pin settings (RS485 Interface Communication)

Reference	Jumper Position	Description
JP30	1-2 are short-circuit	Full-duplex communication
JP31	2-3 are short-circuit	Half-duplex communication

Table 3.5 Switch3 settings

SW3	Setting	Description
SW3-1	ON	RAM Boot mode * Substitute using “xSPI1 boot mode”
SW3-2	OFF	
SW3-3	ON	The number of ATCM wait cycles of CPU0 in the Cortex-R52 is 1 wait cycle.
SW3-4	OFF	
SW3-5	OFF	The number of ATCM wait cycles of CPU1 in the Cortex-R52 is 1 wait cycle.
SW3-6	OFF	The power-supply voltage of the boot peripheral is 3.3 V.
SW3-7	ON	JTAG mode = Normal mode
SW3-8	OFF	(At the time of shipment = OFF)

Table 3.6 Switch2 settings

SW2	Setting	Description
SW2-1	ON	XTALSEL = 'L' Select oscillator for RZ/N2H clock input.
SW2-2	OFF	(At the time of shipment = OFF)
SW2-3	ON	P27_2, P27_3, P27_6, and P31_3 are used as inputs to user DIP switches.
SW2-4	OFF	P13_4, P13_5, and P14_0 are used as RXD3, TXD3, and DE3 of the RS485.
SW2-5	ON	P00_0 to P00_2 are used as control signals for the USB power-supply IC. In this case, set DSW14-1, DSW14-3, and DSW14-5 to ON and DSW14-2, DSW14-4, and DSW14-6 to OFF.
SW2-6	ON	P01_0, P01_2, P01_4 to P01_7, and P02_0 to P02_3 are used as XSPI1 signals.
SW2-7	OFF	(At the time of shipment = OFF)
SW2-8	OFF	(At the time of shipment = OFF)

Table 3.7 Switch5 settings

SW5	Setting	Description
SW5-1	ON	P12_0 to 7, P13_0 to 2 are connected to eMMC.
SW5-2	ON	
SW5-3	ON	P08_6 and P17_4 are used as SD1 control signal.
SW5-4	OFF	(At the time of shipment = OFF)
SW5-5	OFF	(At the time of shipment = OFF)
SW5-6	ON	MDC and MDIO of Ethernet port 2 are connected to GMAC0 (P21_4 and P21_5).
SW5-7	ON	P29_1 to P29_7, P30_0 to P30_4, P30_7, P31_2, P31_4, and P31_5 are used as control signals for Ethernet Port 2.
SW5-8	ON	P00_0 to P00_2, P33_2 to P33_7, and P34_0 to P34_6 are used as control signals for Ethernet Port 3.

Table 3.8 Switch8 settings

SW8	Setting	Description
SW8-1	ON	P03_1_GMAC_RESETOUT2# is used as RESET for Ethernet Port 2.
SW8-2	OFF	

Table 3.9 Switch12 settings

SW12	Setting	Description
SW12-1	OFF	P00_3 is used as P00_3_ETH3_COL of Ethernet Port 3.
SW12-2	ON	
SW12-3	OFF	P11_0 is used as P11_0_ESC_RESETOUT# of Ethernet Port 0 and 1.
SW12-4	ON	
SW12-5	OFF	P03_2 is used as P03_2_GMAC_RESETOUT3# of Ethernet Port 3.
SW12-6	ON	
SW12-7	OFF	P03_1 is used as P03_1_GMAC_RESETOUT2# of Ethernet Port 2. In this case, set DSW8-1 to ON and DSW8-2 to OFF.
SW12-8	ON	

Table 3.10 Switch13 settings

SW13	Setting	Description
SW13-1	ON	P26_7 is used as P26_7_ETH1_RXER of Ethernet Port 1.
SW13-2	OFF	
SW13-3	ON	P27_0 is used as P27_0_ETH1_CRIS of Ethernet Port 1.
SW13-4	OFF	
SW13-5	ON	P27_1 is used as P27_1_ETH1_COL of Ethernet Port 1.
SW13-6	OFF	
SW13-7	OFF	P13_7 is used as MDINT of Ethernet Port 2.
SW13-8	ON	

Table 3.11 Switch15 settings

SW15	Setting	Description
SW15-1	OFF	P22_6 is used as P22_6_SD0_WP.
SW15-2	ON	
SW15-3	OFF	P22_5 is used as P22_5_SD0_CD.
SW15-4	ON	
SW15-5	OFF	P14_7 is used as P14_7_USER_LED1(LED9)
SW15-6	ON	
SW15-7	OFF	- (At the time of shipment = OFF)
SW15-8	OFF	P14_6 is used as P14_6_USER_LED0(LED8)
SW15-9	OFF	
SW15-10	ON	

Table 3.12 Switch17 settings

SW17	Setting	Description
SW17-1	OFF	P03_0 is used as USER_LED3(LED11).
SW17-2	ON	
SW17-3	OFF	P02_7 is used as USER_LED2(LED10).
SW17-4	ON	
SW17-5	OFF	P02_6 is used as P02_6_SD0_IOVS.
SW17-6	ON	
SW17-7	OFF	- (At the time of shipment = OFF)
SW17-8	ON	P02_5 is used as P02_5_SD0_PWEN.

Table 3.13 Switch18 settings

SW18	Setting	Description
SW18-1	ON	P22_7 is used as ESC_LINKACT0(LED5).
SW18-2	OFF	
SW18-3	ON	P23_0 is used as ESC_LINKACT1(LED6).
SW18-4	OFF	
SW18-5	ON	P14_3 is used as ESC_LINKACT2(LED7).
SW18-6	OFF	
SW18-7	ON	P31_6 is used as ESC_LED RUN(LED3).
SW18-8	OFF	
SW18-9	ON	P18_1 is used as ESC_LEDERR(LED4).
SW18-10	OFF	

3.3 Setting the Board

3.3.1 Debug connection

Setting the board for running sample program is shown below.

Build and run the sample code on the RZ/N2H Evaluation board by following the steps below.

Both loading into RAM and flash can be done using IAR Embedded Workbench or e² studio.

1. Connect the debugger to the header "CN24" on the RZ/N2H Evaluation board.

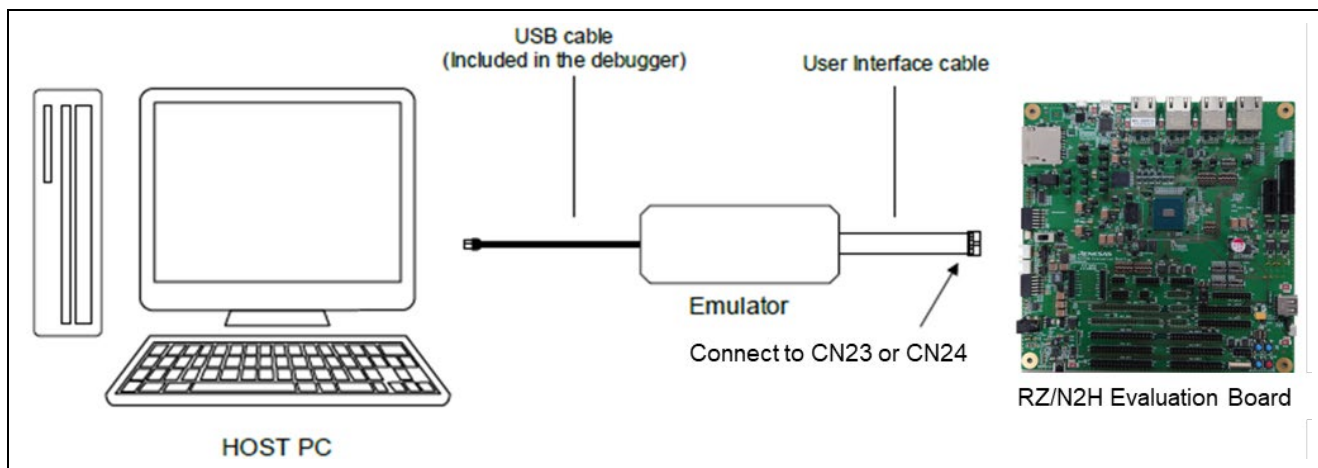


Figure 3.2 RZ/N2H Evaluation board debug connection diagram.

When using J-Link OB, connect the USB cable to the header "CN26" and set "JP40" to open.

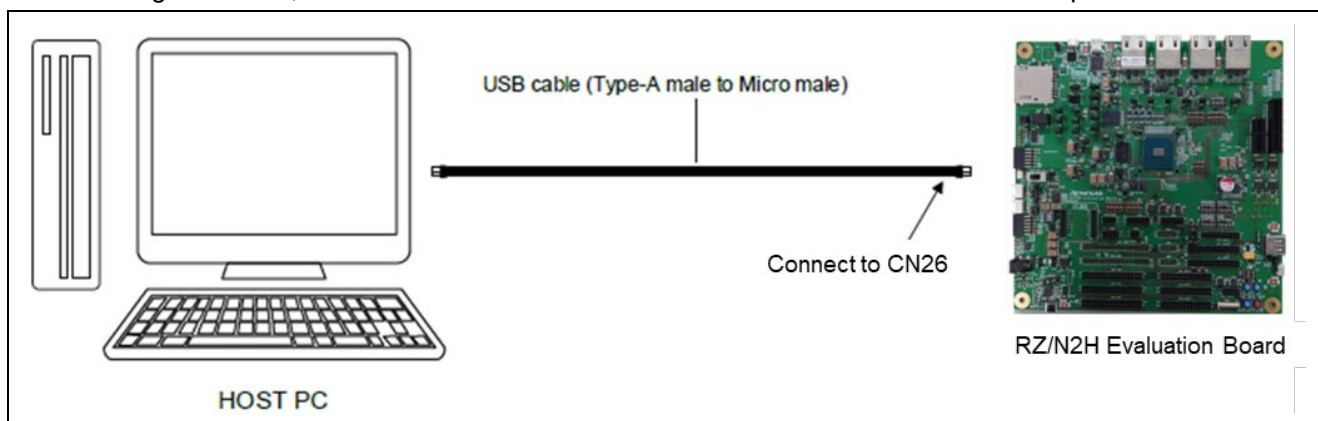


Figure 3.3 RZ/N2H Evaluation board debug connection diagram (J-Link OB)

2. When connecting to the AC/DC adapter, connect it to the connector "J1" on the RZ/N2H Evaluation board.

3.3.2 Serial board connection

Connect the PC to the RZ/N2H board as shown below.

Power is supplied by connecting a USB Micro-C cable to the board.

For Modbus serial communication, use RS485 connector and connect to PC with RS-485 cable.

Connect the RS485 A cable to CN36-6, the B cable to CN36-3, and the G cable to CN36-10.

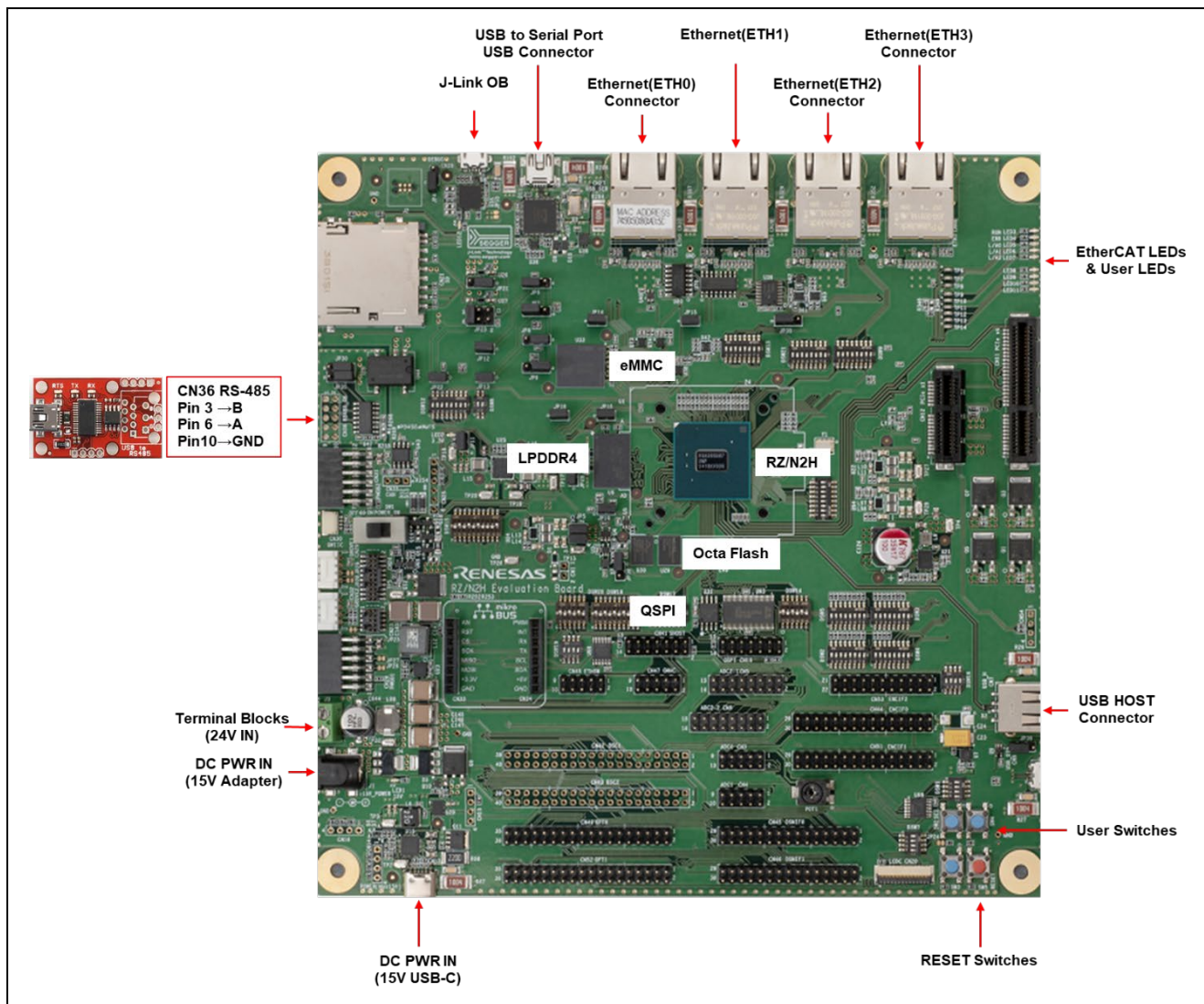


Figure 3.4 RZ/N2H Evaluation board layout.

4. Setup a demo tool

1. Open “**ModbusDemoApplication.exe**” which is included in this package.
2. In the case of RTU communication:
“Connection” is selected to Serial Client (“Serial Master”) or Serial Server (“Serial Slave”), and set serial Port No (for example, “COM3”), Baud Rate (for example, “115200bps”), Communication mode (“RTU”), Parity (for example, “NONE Parity”), and Stop Bit (for example, “1 stop bit”).

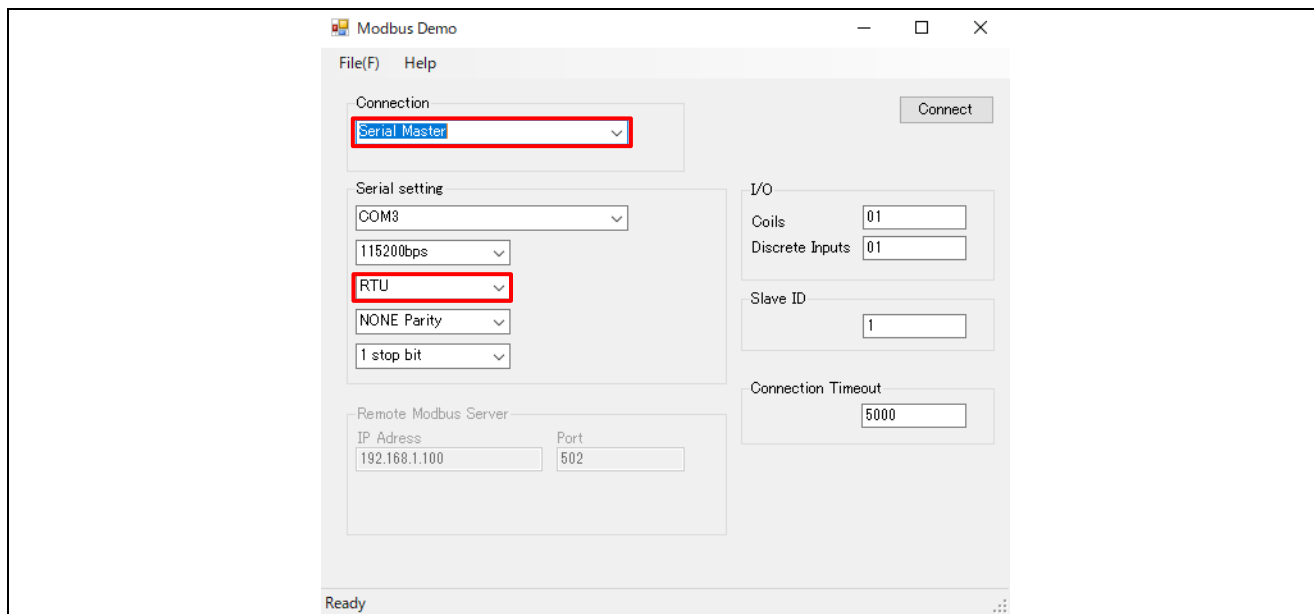


Figure 4.1 ModbusDemoApplication setting for RTU.

3. In the case of ASCII communication:
“Connection” is selected to Serial Client (“Serial Master”) or Serial Server (“Serial Slave”), and set serial Port No (for example, “COM3”), Baud Rate (for example, “115200bps”), Communication mode (“ASCII”), Parity (for example, “NONE Parity”), and Stop Bit (for example, “1 stop bit”).

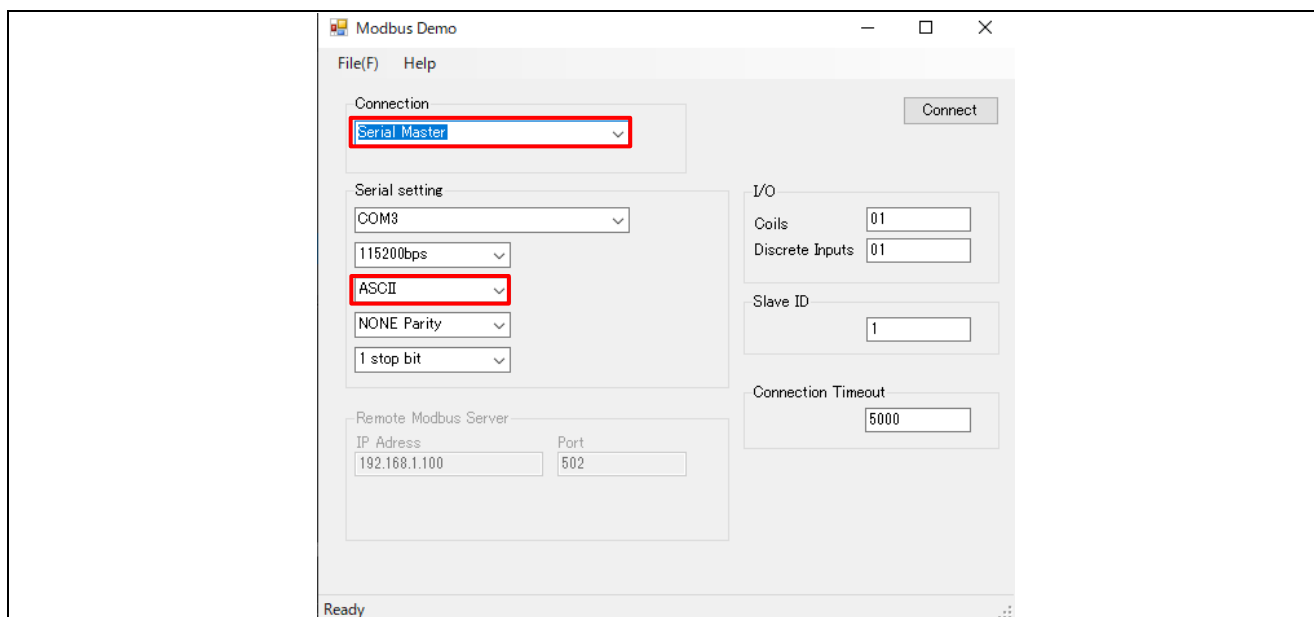


Figure 4.2 ModbusDemoApplication setting for ASCII.

5. Running the sample application

Refer to Section 3.3 Setting the Board for board settings.

The setup differs depending on the IDE.

- When using e² studio, refer to section 5.1.
- When using EWARM, refer to section 5.2.

5.1 Setup sample project for e² studio

Build the sample code and load it into RAM using Renesas Electronics e² studio.

Note). Please install e² studio and adapt the RZ_FSP_Packs_v4.1.0 in advance.

Refer to the latest getting started guide. (r01an6434ejxxxx-rzt2-rzn2-fsp-getting-started.pdf)

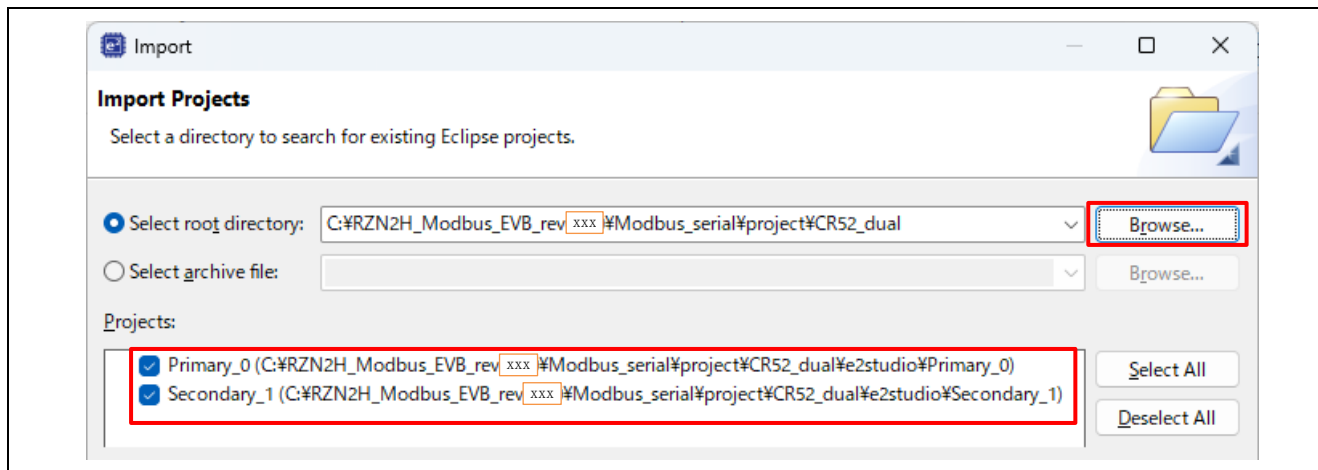
This package includes the following projects.

Project		CPU
Dual-core project (CR52_dual)	Primary_0	CR52_0
	Secondary_1	CR52_1
Dual-core project (CR52-CA55_dual)	Primary_0	CR52_0
	Secondary_1	CA55_2

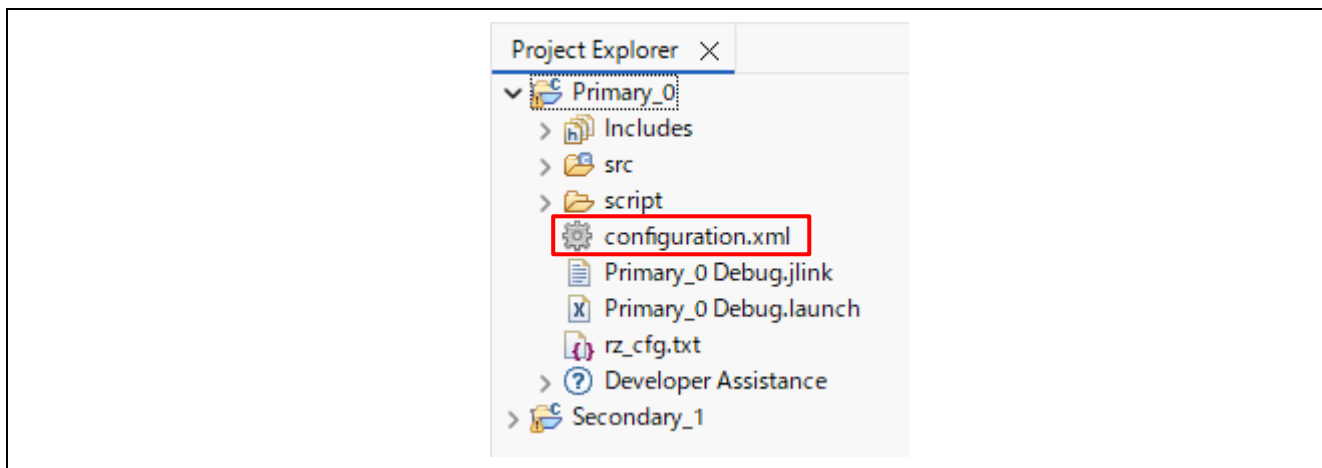
5.1.1 Dual core project startup procedure (CR52_0, CR52_1), (CR52_0, CA55_2)

1. Import the sample project. After the program is started, by selecting [File] → [Import] → [Existing Projects into Workspace]. Check the "select root directory" and click "Browse..." button.
→ Select "RZN2H_Modbus_EVB_rev0410\Modbus_serial\project\xxxx_dual" folder. → Check "Primary_0" and "Secondary_1" → [Finish].

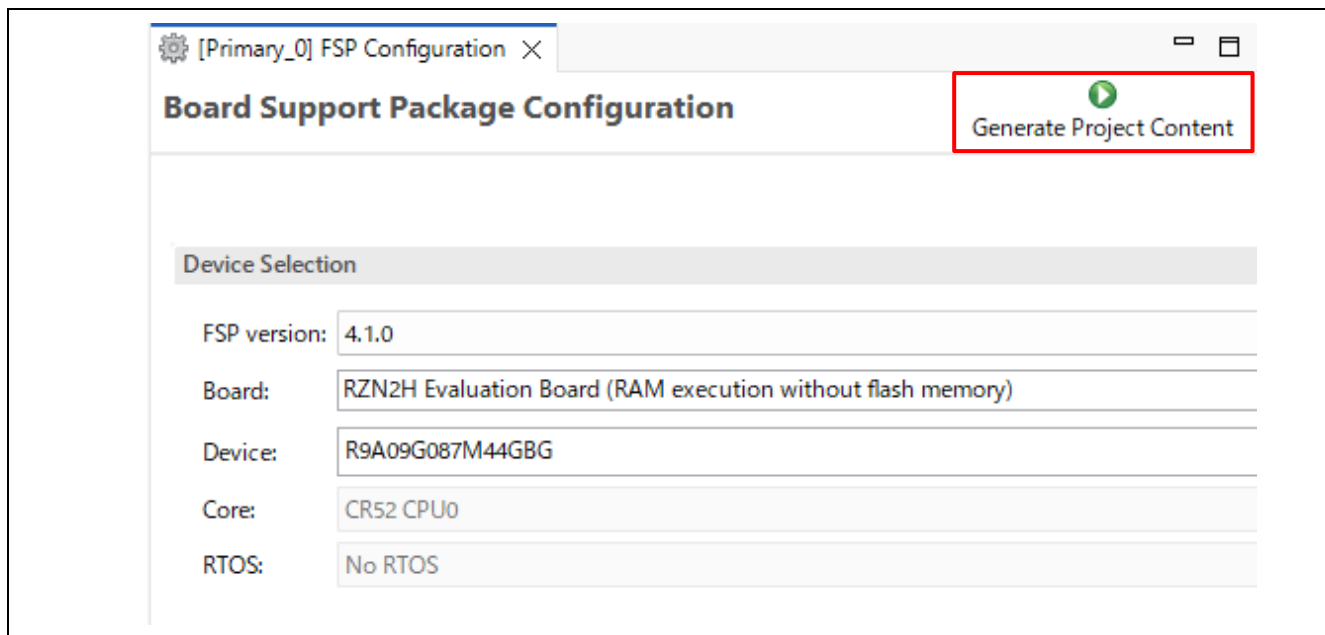
Note), **xxxx** is either "CR52" or "CR52-CA55", select one.



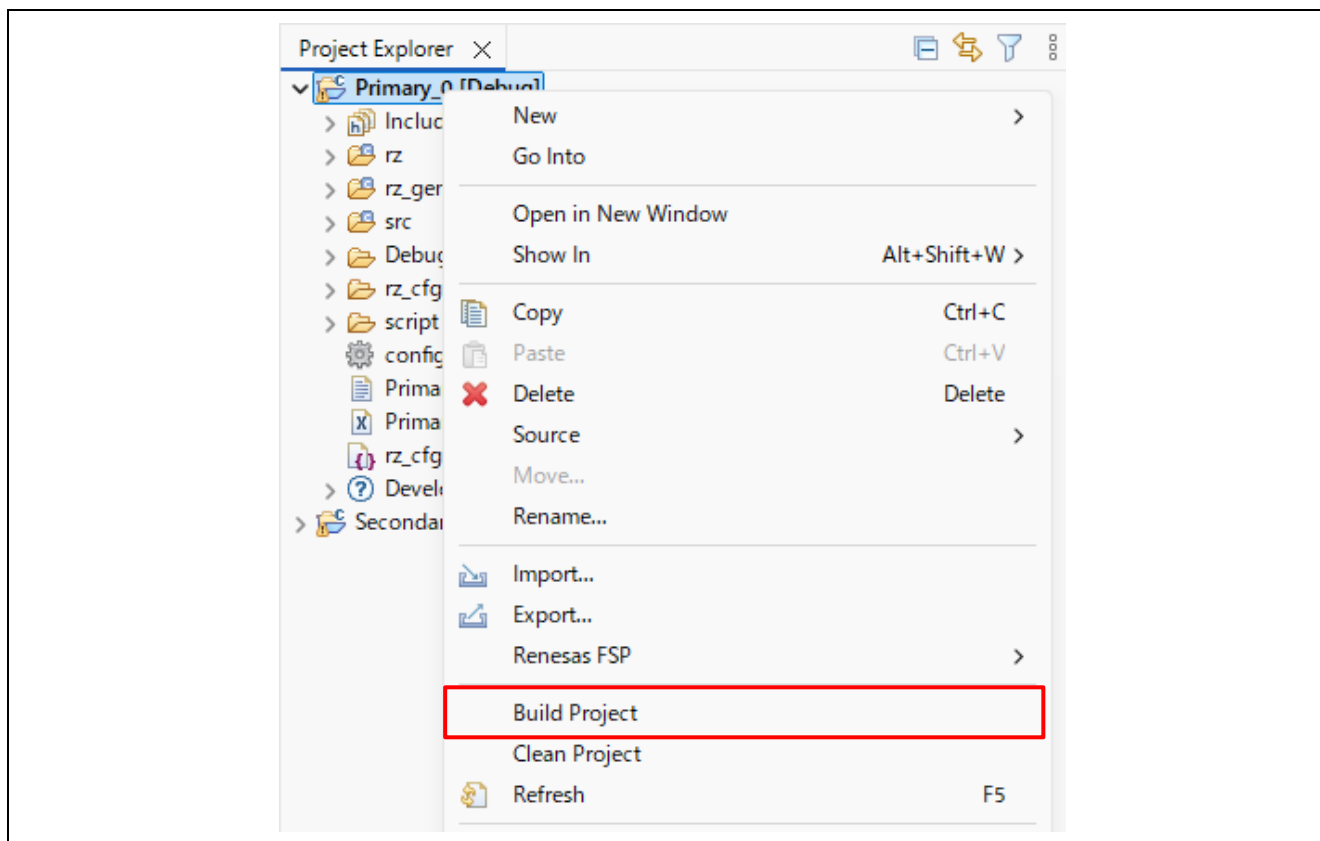
2. Open "configuration.xml" in the "Primary_0" project



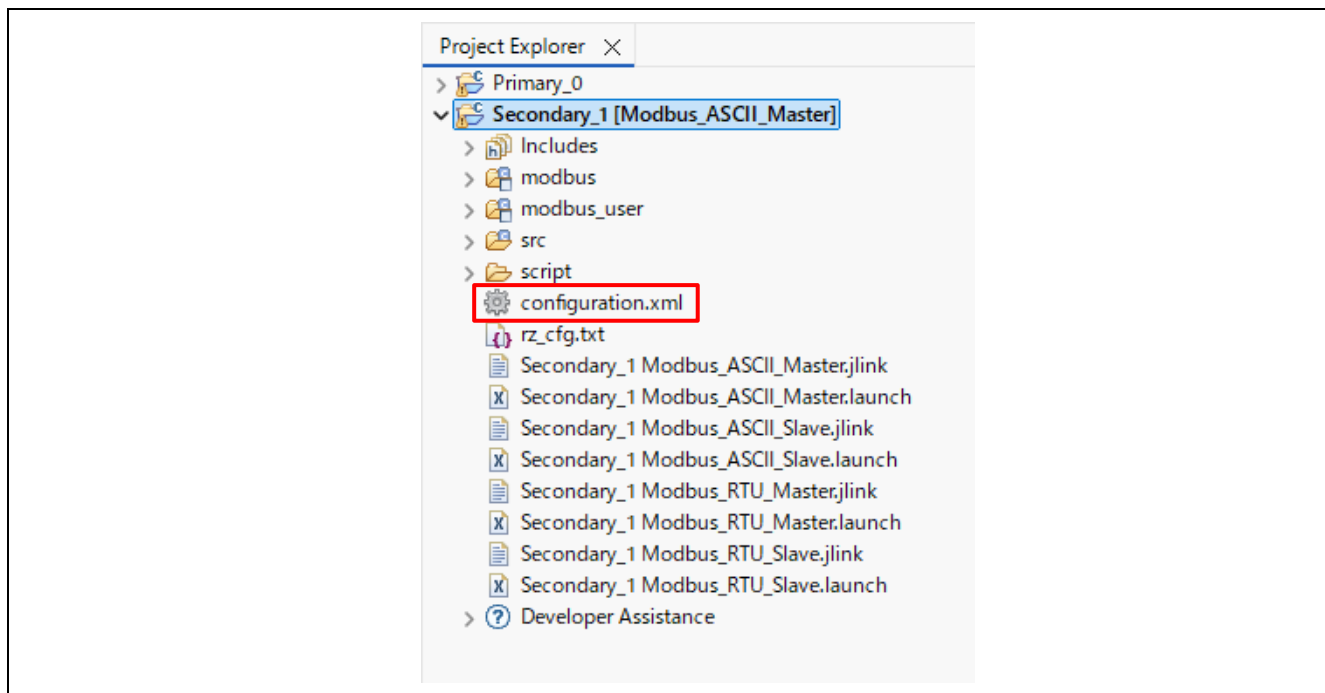
3. Check the boot mode project from BSP tab (following is RAM boot mode). And generate the code with **"Generate Project Content"**.



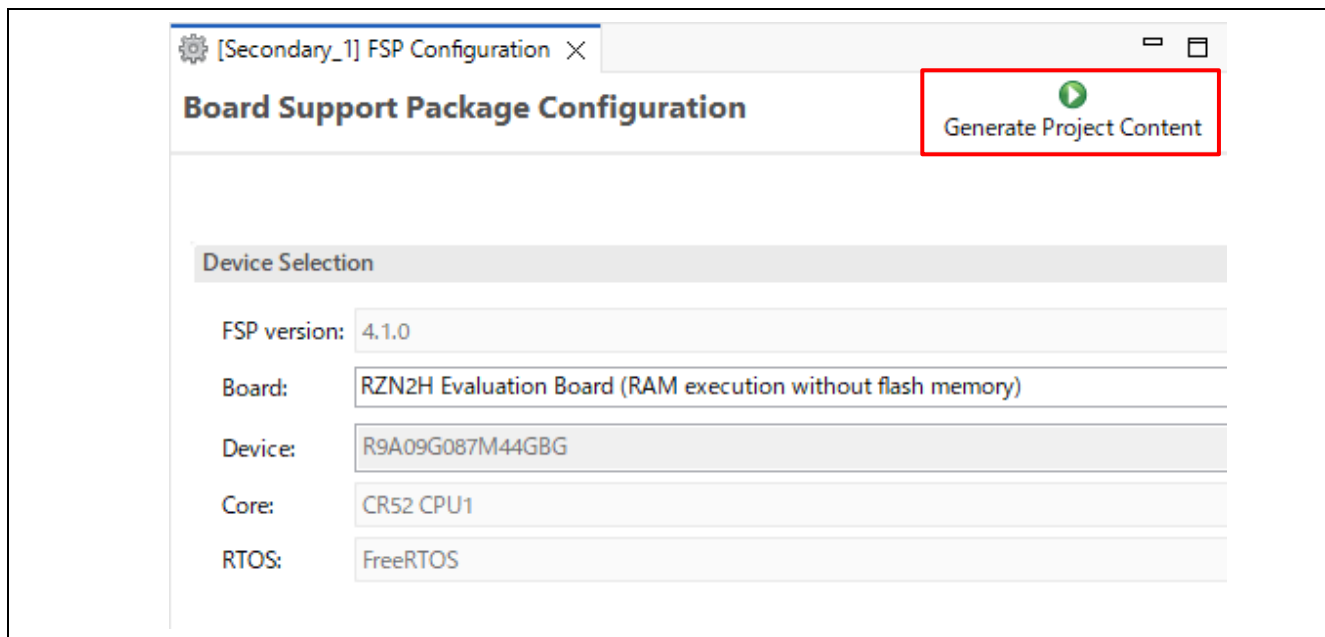
4. Select the **"Primary_0"** project and execute the build.



5. Open "configuration.xml" in the " **Secondary_1** " project



6. Check the boot mode project from BSP tab (following is RAM boot mode). And generate the code with "Generate Project Content".



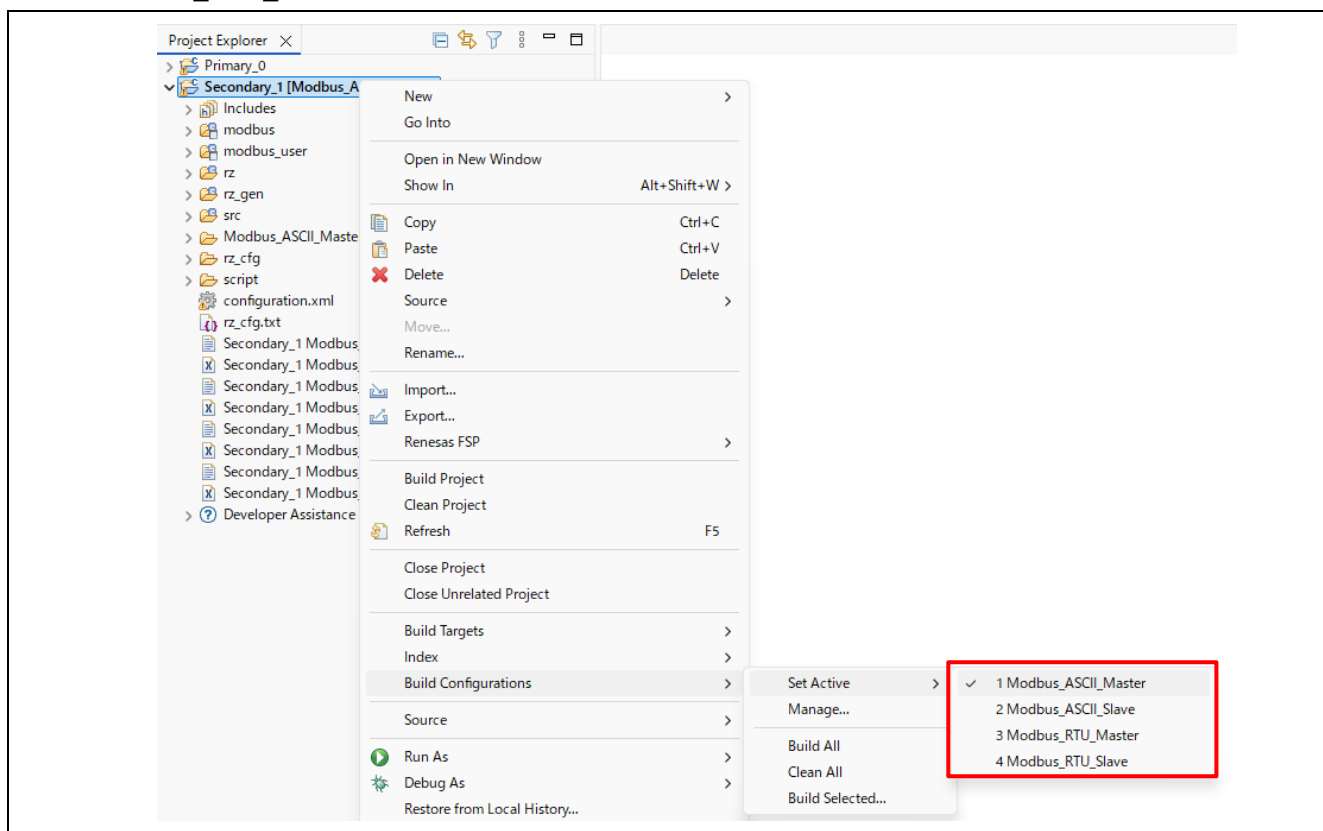
7. Select the following features from "Build Configuration".

"Modbus_ASCII_Master"

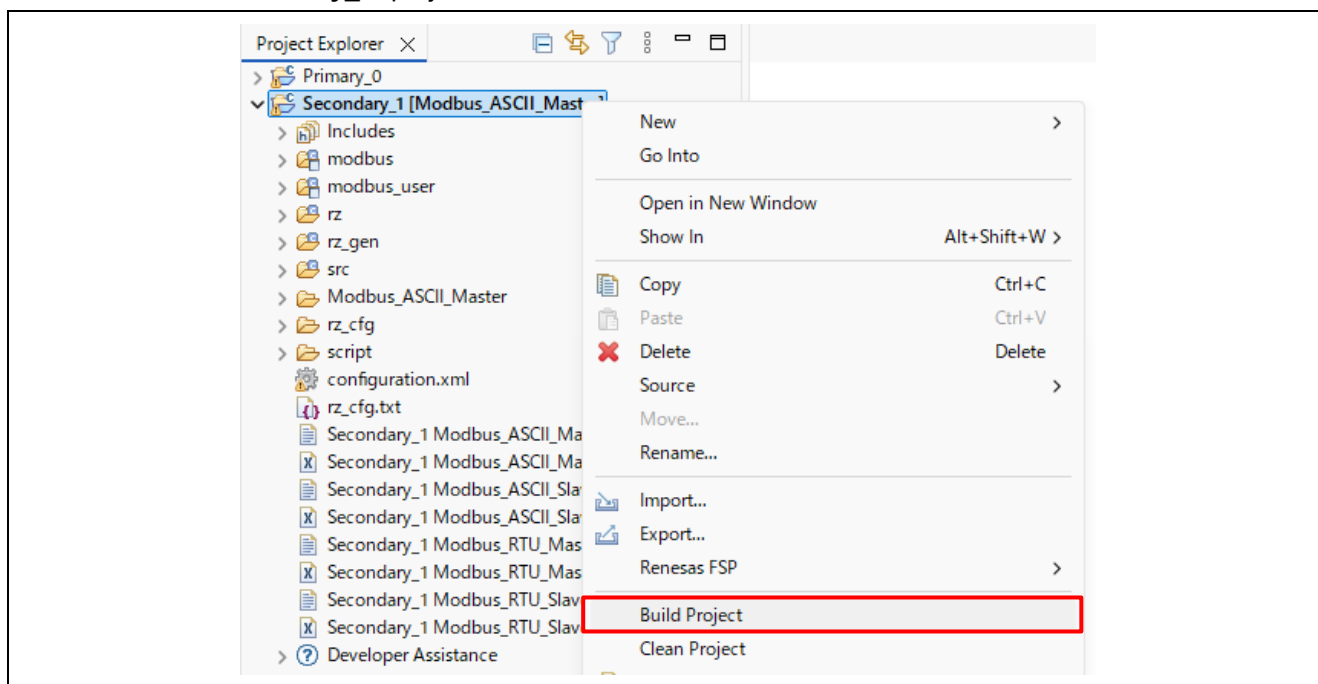
"Modbus_ASCII_Slave"

"Modbus_RTU_Master"

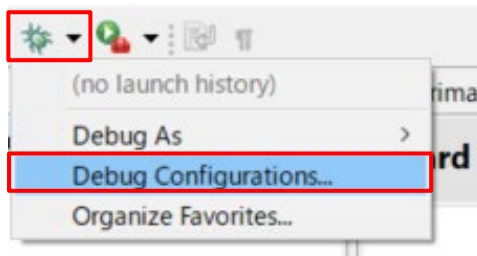
"Modbus_RTU_Slave"



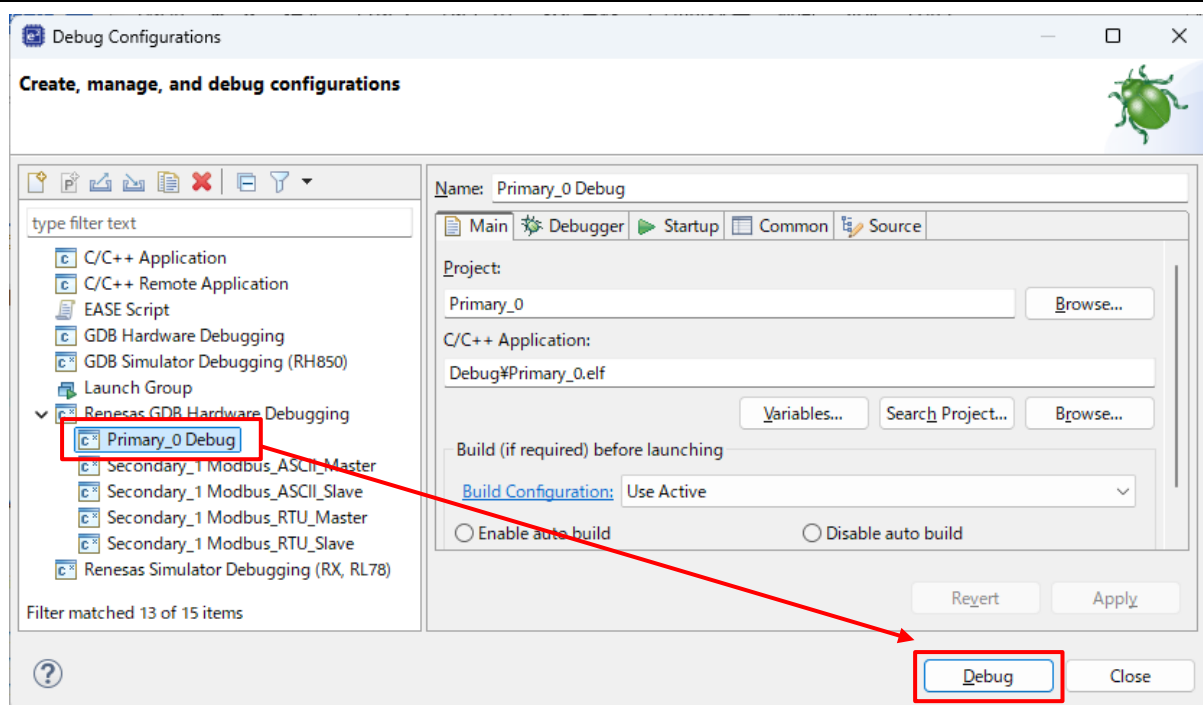
8. Select the "Secondary_1" project and execute the build.



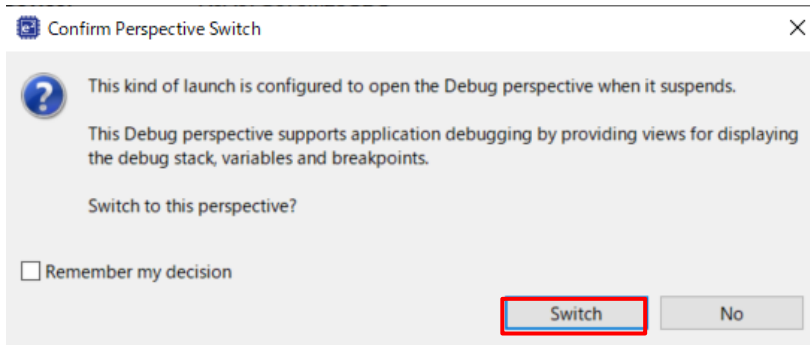
9. Press the **"RESET"** switch of the RSK + RZN2H board.
10. After connecting the board and J-Link, start debugging in the following procedure. Select the drop-down menu next to the bug icon and selecting **"Debug Configurations..."**.



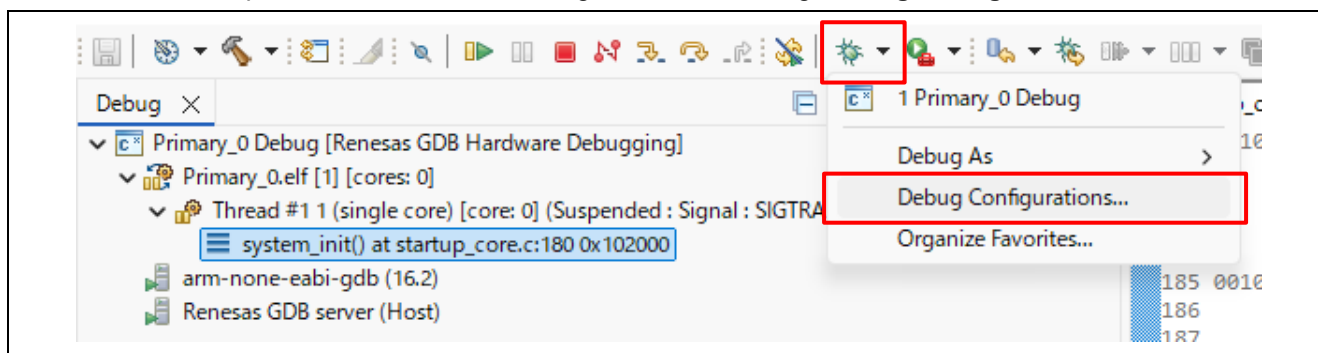
[Renesas GDB Hardware Debugging] → [Primary_0 Debug] item, then press [Debug].



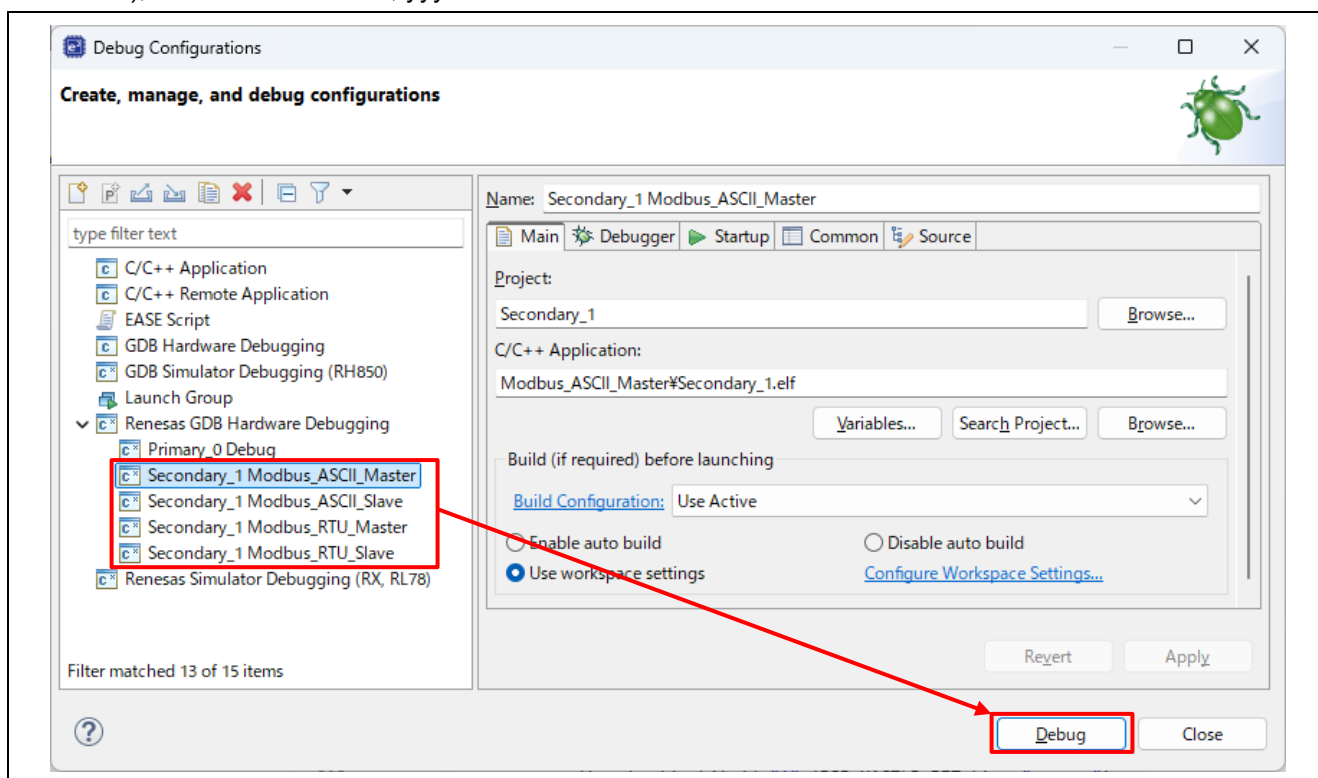
The following dialog will appear, so switch to the debug screen.



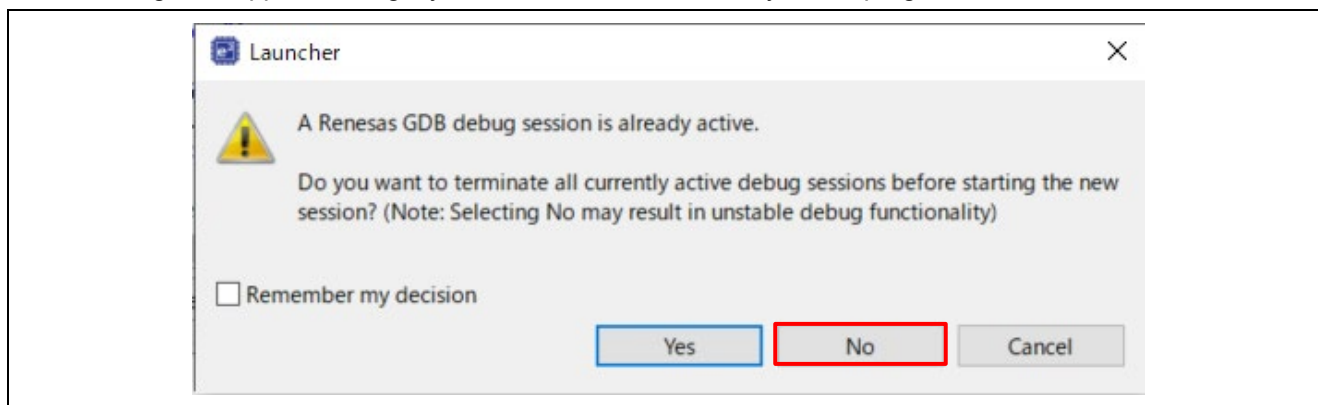
11. Select the drop-down menu next to the bug icon and selecting “**Debug Configurations...**”



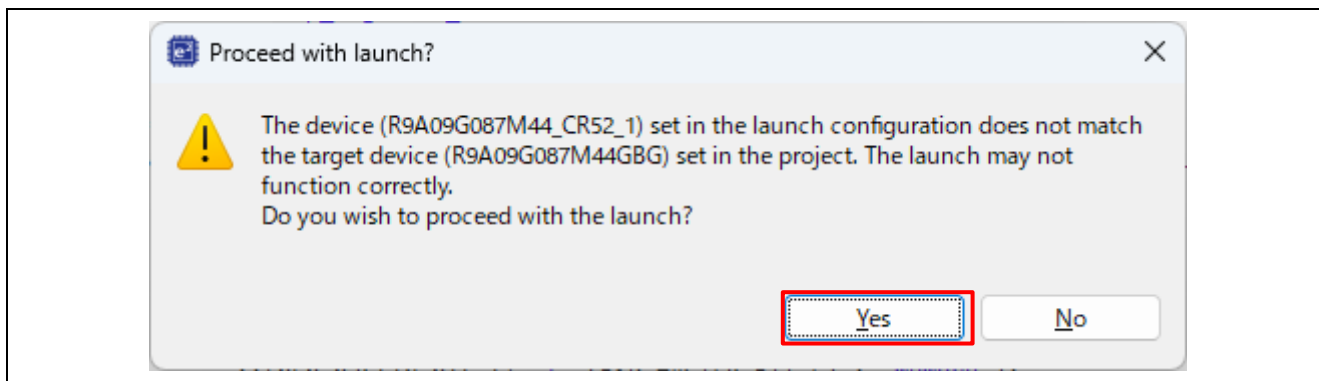
[Renesas GDB Hardware Debugging] → [Secondary_1 **Modbus_xxx_yyy**] item, then press [Debug].
Note), xxx is RTU or ASCII, yyy is Master or Slave



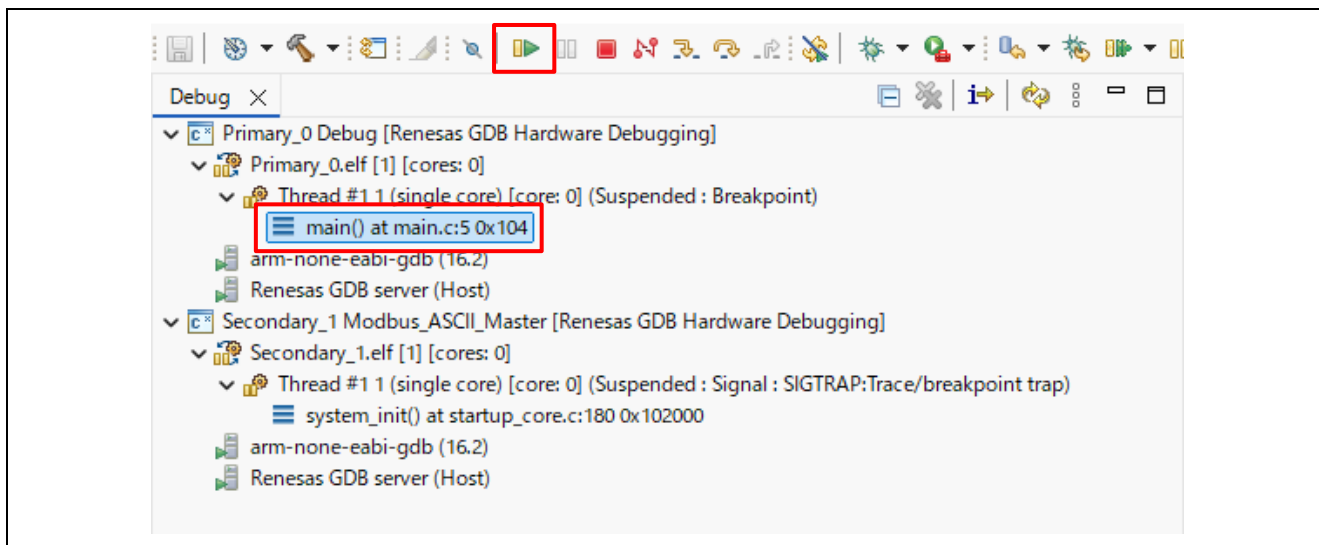
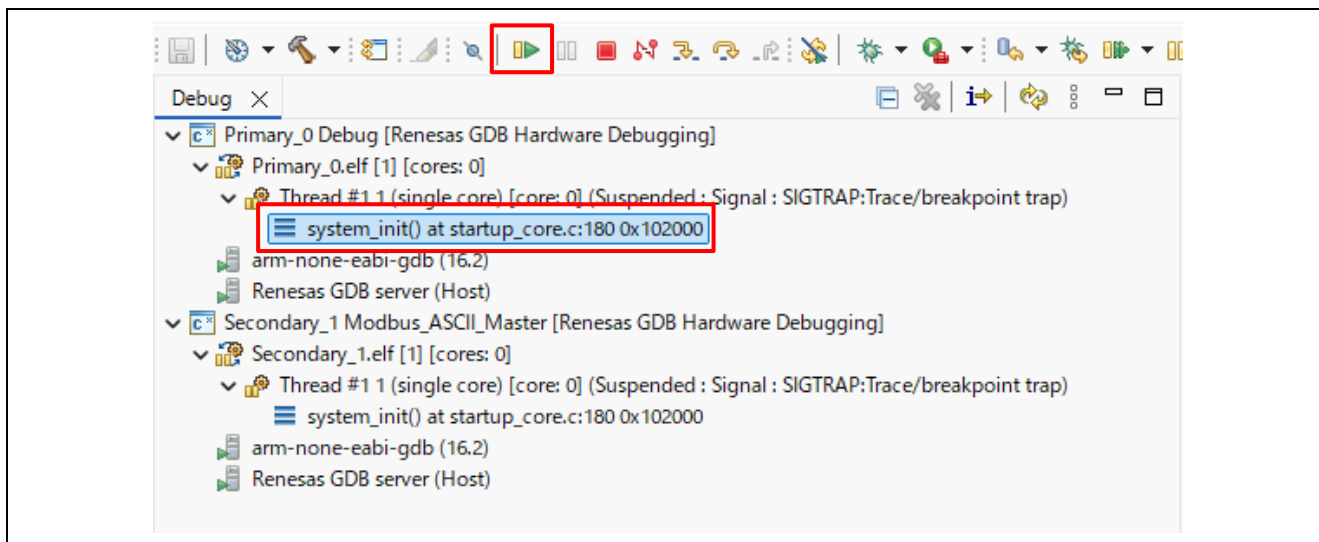
12. Message will appear asking if you want to close all currently active programs. Select “**No.**”



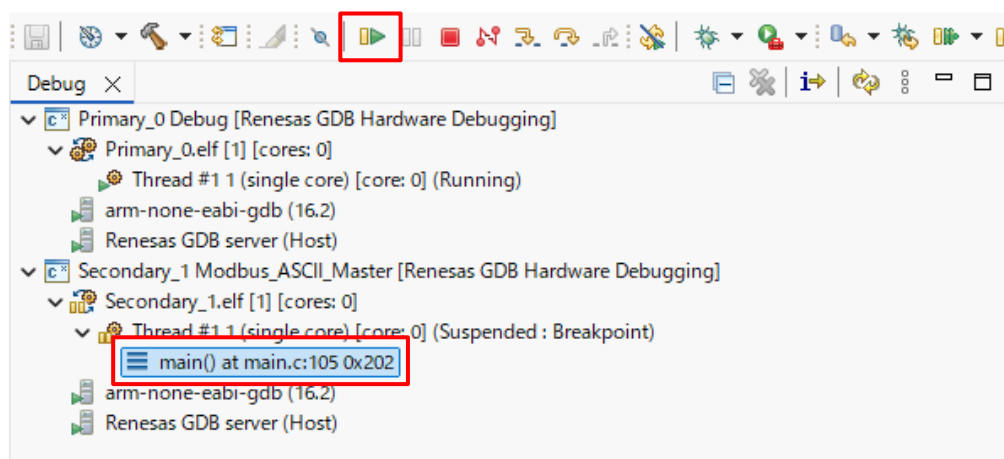
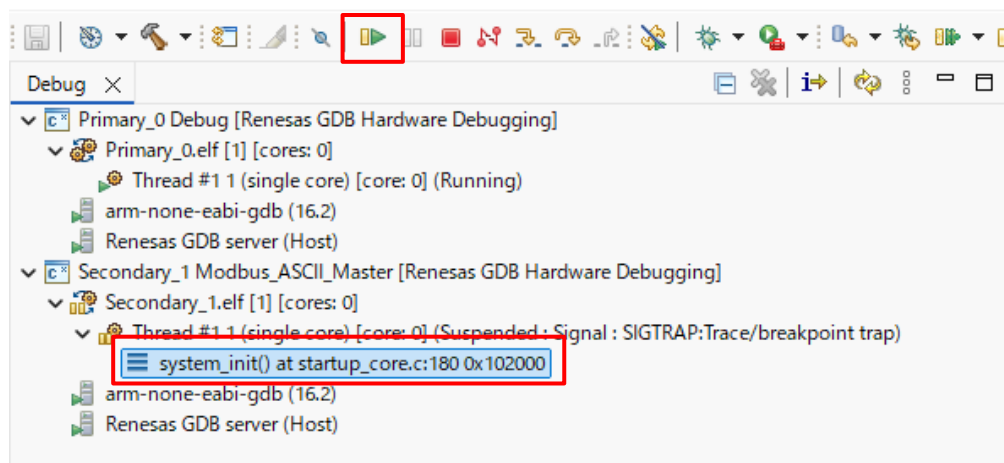
13. Message will appear asking if you want to continue launching, select "**Yes**".



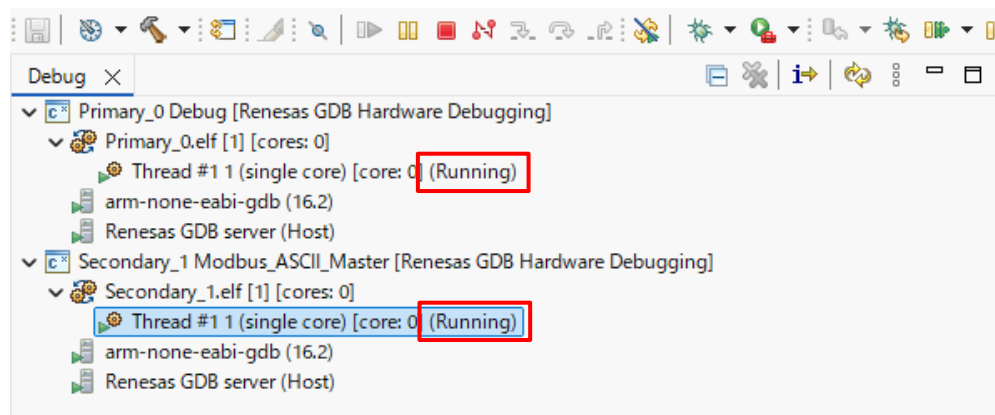
14. Press the "**Resume**" button. "**Primary_0**" debug will start and the program will be suspended in main.c. Press the "**Resume**" button again. Program will run.



15. Press the **"Resume"** button. **"Secondary_1"** debug will start and the program will be suspended in main.c. Press the **"Resume"** button again. Program will run.



16. Finally, the **"Primary_0"** and **"Secondary_1"** cores will start up and the program will run.



5.2 Setup sample project for EARM

Build the sample code and load it into RAM using IAR Systems EARM.

Note). Please install EARM and adapt the RZ_FSP_Packs_v4.1.0 in advance.

Refer to the latest getting started guide. (r01an6434ejxxx-rzt2-rzn2-fsp-getting-started.pdf)

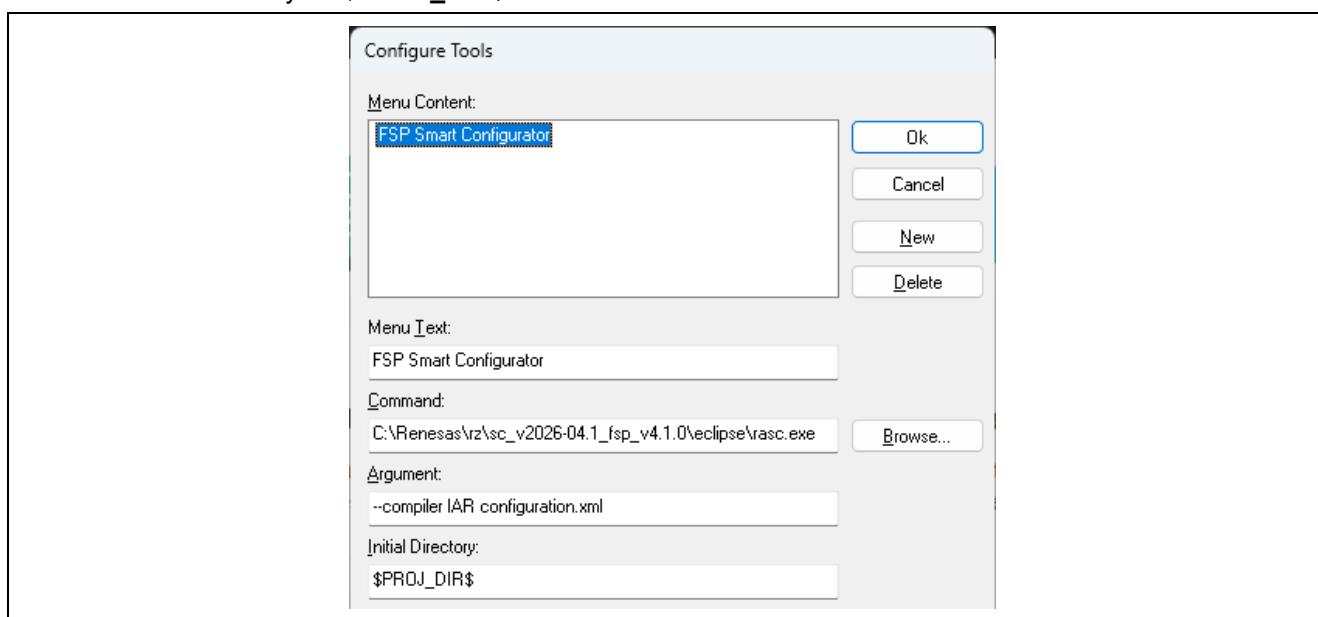
This package includes the following projects.

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Dual-core project (CR52_dual)	Primary_0	CR52_0
	Secondary_1	CR52_1
Dual-core project (CR52-CA55_dual)	Primary_0	CR52_0
	Secondary_1	CA55_2

Note). In EARM, set the Smart Configurator startup settings as follows.

[Tools] -> [Configure Tools]

- Menu Text: **FSP Smart Configurator**
- Command: **\$RASC_EXE_PATH\$** (The following example is "C:\Renesas\rz\sc_v2026-04.1_fsp_v4.1.0\eclipse\rasc.exe")
- Argument: **--compiler IAR configuration.xml**
- Initial Directory: **\$PROJ_DIR\$**



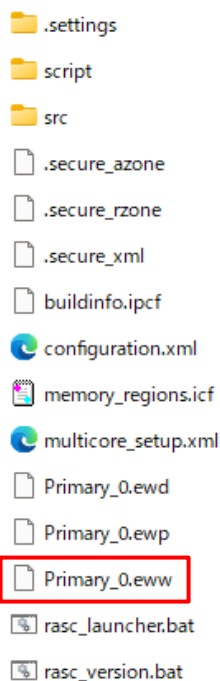
Edit "buildinfo.ipcf" file. Open the buildinfo.ipcf file and edit "RASC_EXE_PATH" to match the installation path of "rasc.exe".

```
<customArgVars>
  <group name="RA Smart Configurator">
    <argVar>
      <name>RASC_EXE_PATH</name>
      <value>C:\Renesas\rz\sc_v2026-04.1_fsp_v4.1.0\eclipse\rasc.exe</value>
    </argVar>
    <argVar>
      <name>RASC_DEVICE_FAMILY</name>
      <value>rz</value>
    </argVar>
  </group>
</customArgVars>
```

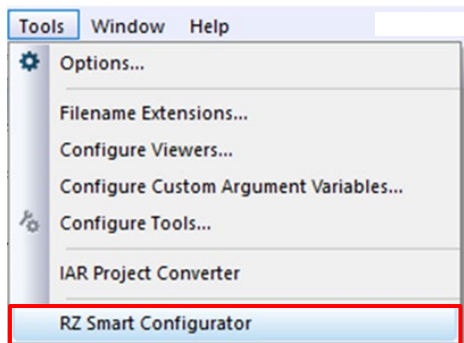
5.2.1 Dual core project startup procedure (CR52_0, CR52_1), (CR52_0, CA55_2)

1. Open the sample project.
"RZN2H_Modbus_EVB_rev0410\Modbus_serial\project\xxxx_dual\ewarm\Primary_0\Primary_0.eww"

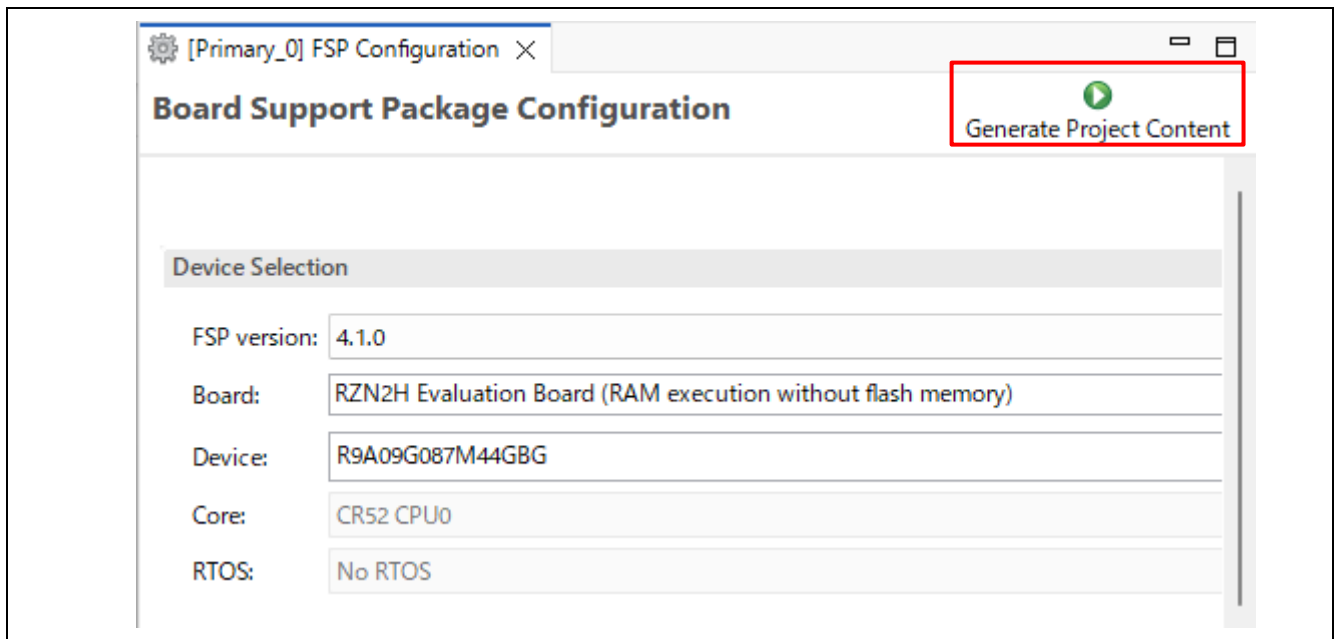
Note), **xxxx** is either "CR52" or "CR52-CA55", select one.



2. Open the "RZ Smart Configurator"

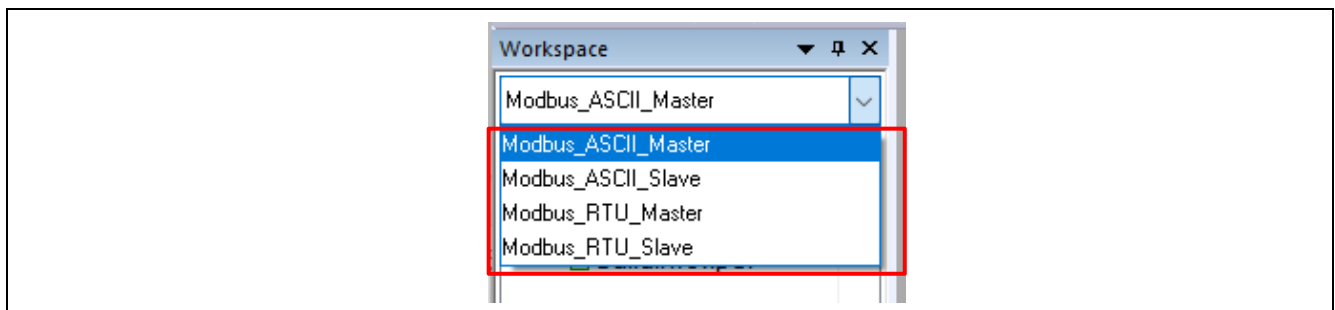


3. Check the boot mode project from BSP tab (following is RAM boot mode). And generate the code with **"Generate Project Content"**.

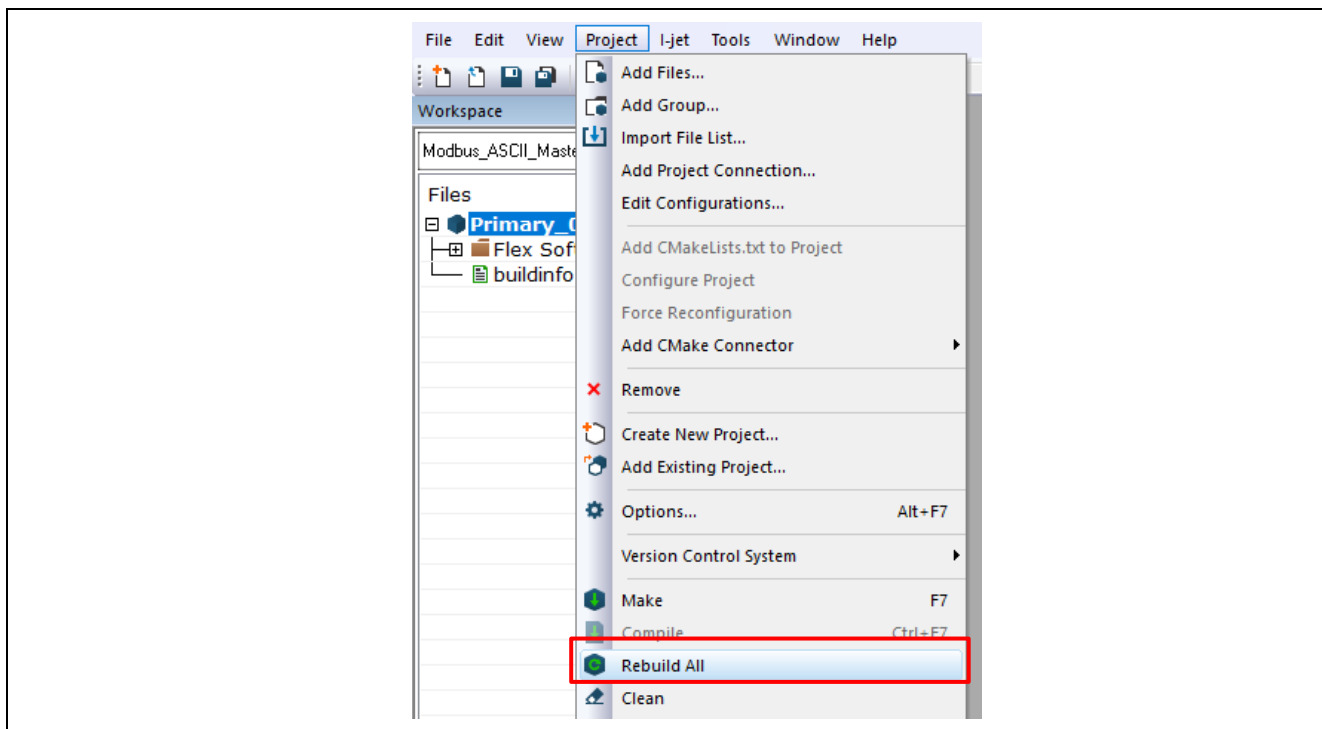


4. Select the following functions from drop-down menu.

"Modbus_ASCII_Master"
"Modbus_ASCII_Slave"
"Modbus_RTU_Master"
"Modbus_RTU_Slave"

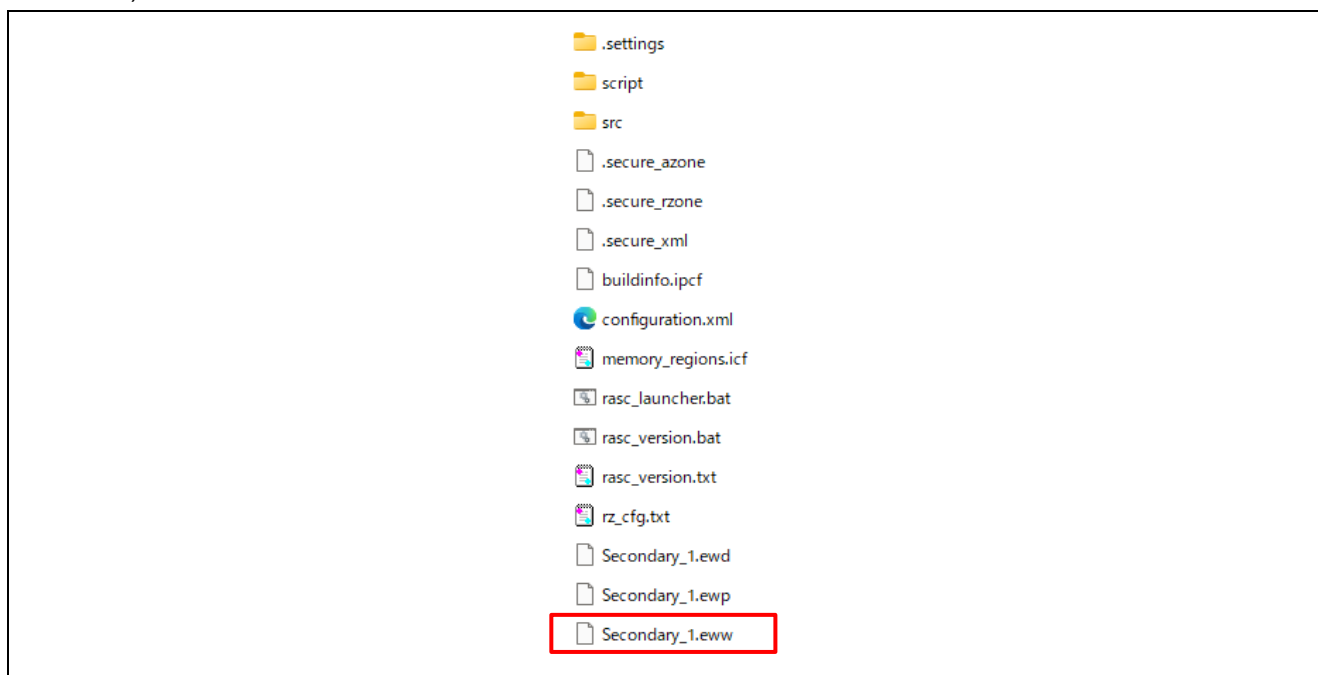


5. Select the “**Rebuild All**” item from the “Project” menu to rebuild the project.

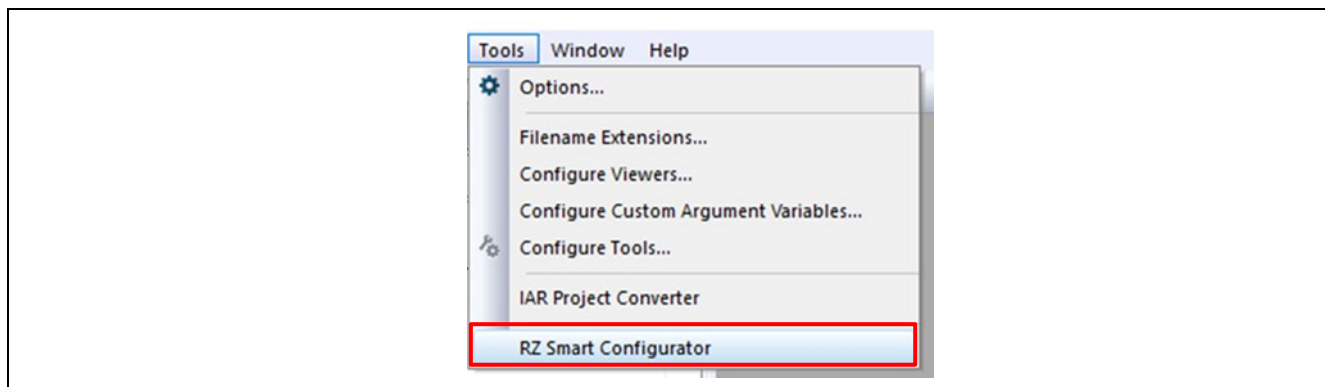


6. When the building is complete, close the “**Primary_0**” project.
7. Open the sample project.
“RZN2H_Modbus_EVB_rev0410\Modbus_serial\project\xxxx_dual\ewarm\Secondary_1\Secondary_1.eww”

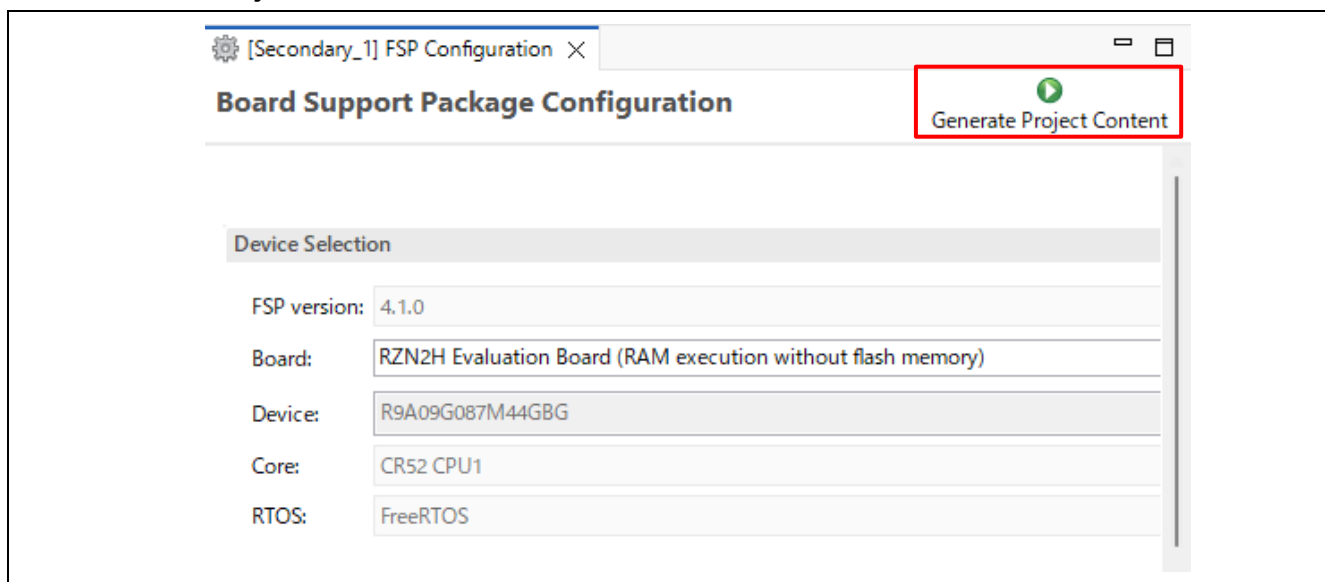
Note), **xxxx** is either “CR52” or “CR52-CA55”, select one.



8. Open the "RZ Smart Configurator"

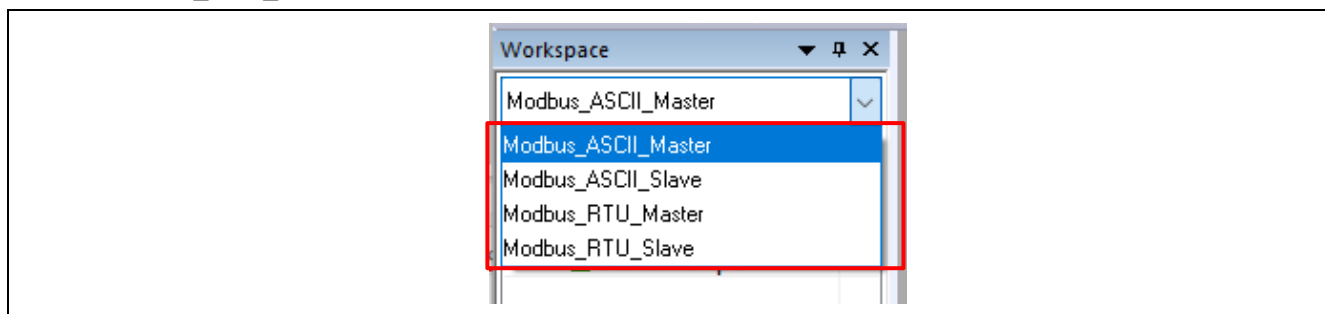


9. Check the boot mode project from BSP tab (following is RAM boot mode). And generate the code with "Generate Project Content".

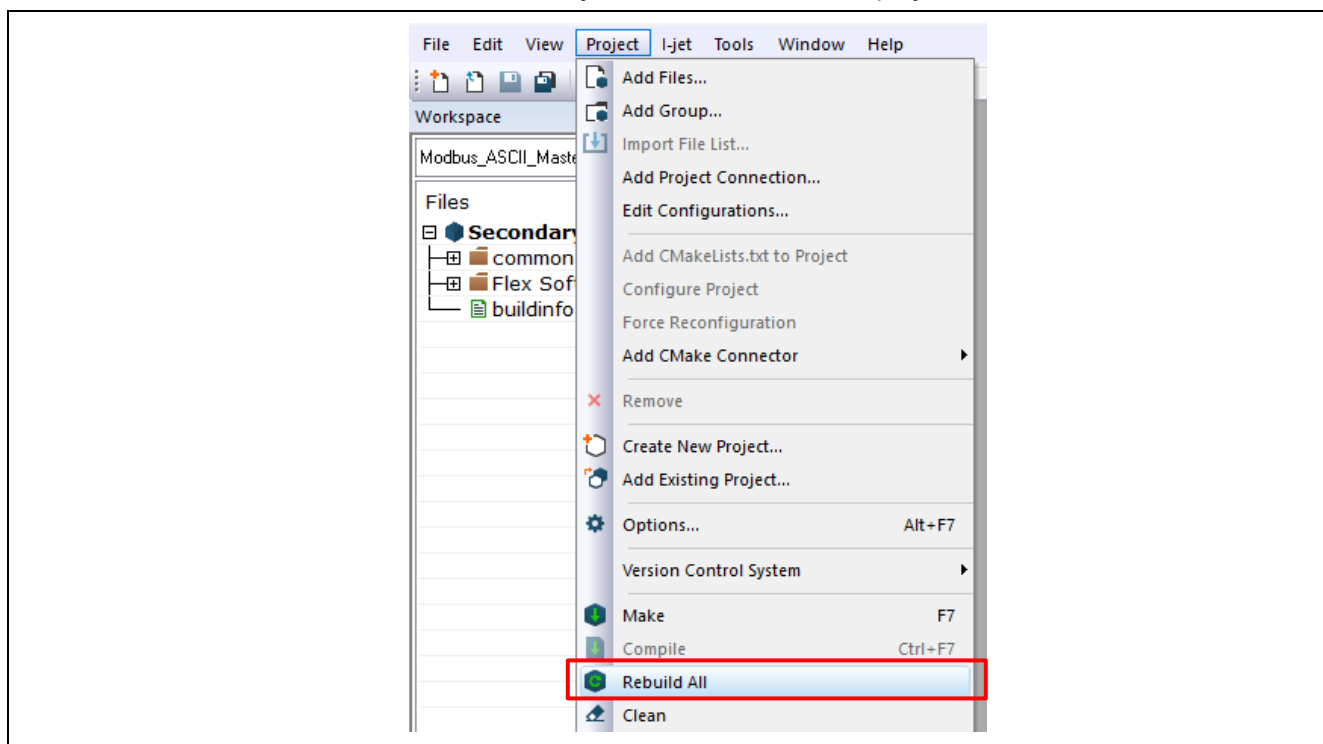


10. Select the following functions from drop-down menu in the same way as for a Primary_0 project.

"Modbus_ASCII_Master"
"Modbus_ASCII_Slave"
"Modbus_RTU_Master"
"Modbus_RTU_Slave"



11. Select the “**Rebuild All**” item from the “Project” menu to rebuild the project.



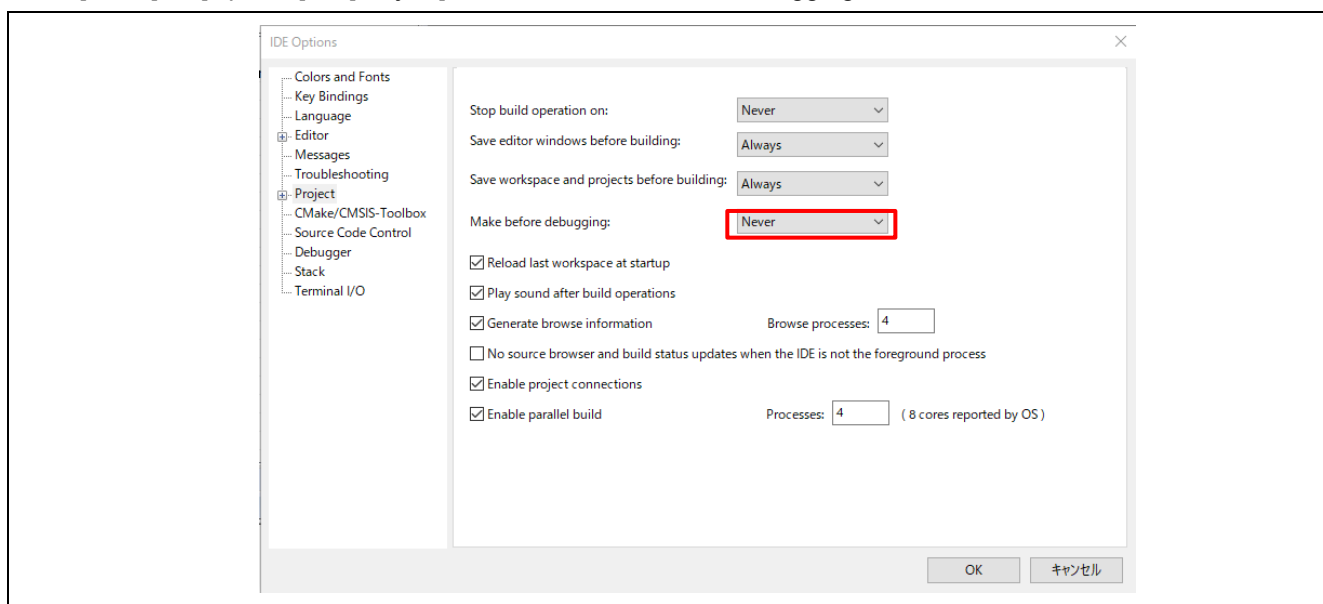
12. When the building is complete, close the “**Secondary_1**” project.

13. Press the “**RESET**” switch of the RSK + RZN2H board.

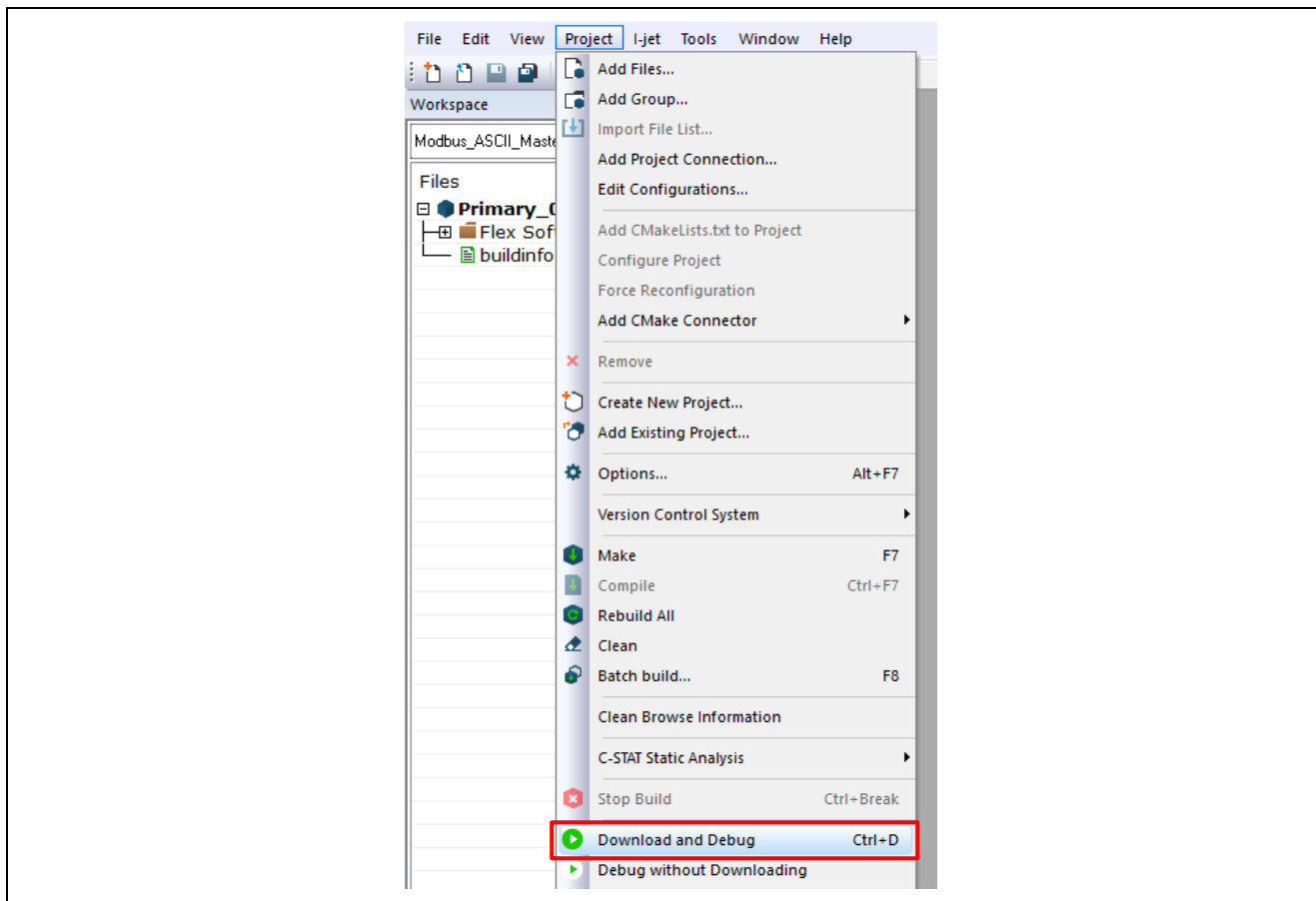
14. Start the “**Primary_0**” project again.

15. Check your debugger options settings.

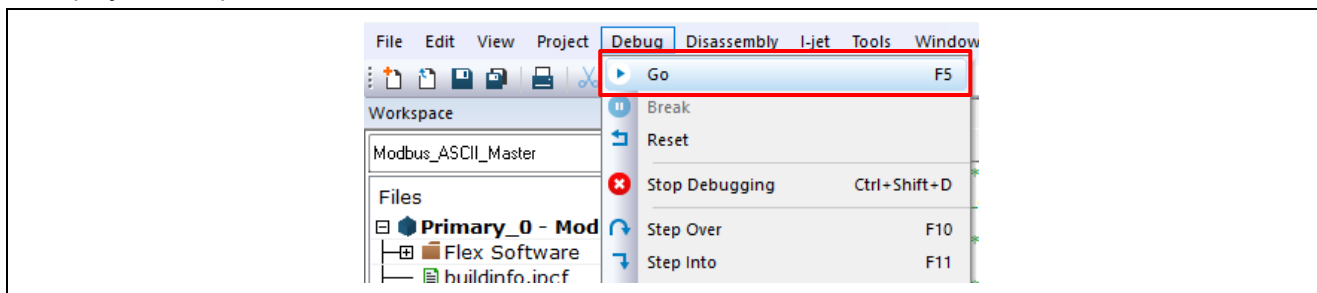
[Tools] → [Options] → [Project] item, Set "Make before debugging" to "Never".



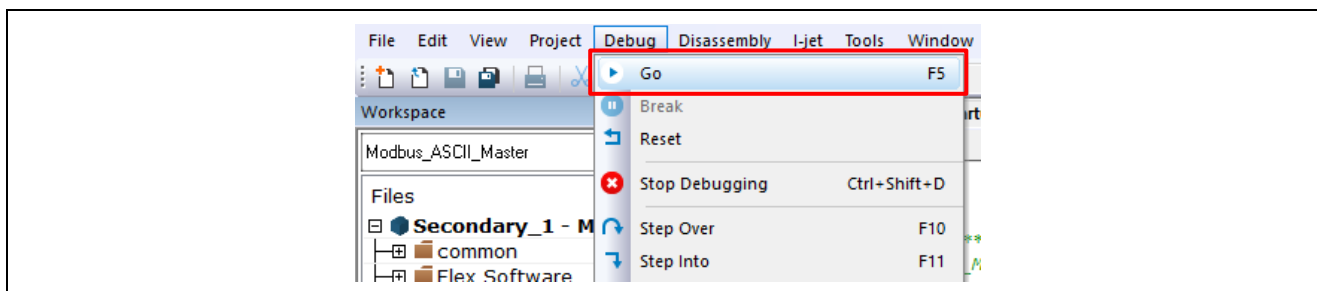
16. After connecting the board and I-jet, click the “Download and Debug button” on the Project toolbar. When run “**Download and Debug**”, the “**Secondary_1**” debug screen will also launch at the same time.



17. First, press the "Resume" button for the “Primary_0” project. Program will run, and “Secondary_1” project will open.



18. Next, press the "Resume" button for the “Secondary_1” project. The program will run.



5.3 Demonstration

5.3.1 Server Application

Users can see the simple demonstration using this Modbus protocol stack in this sample project.

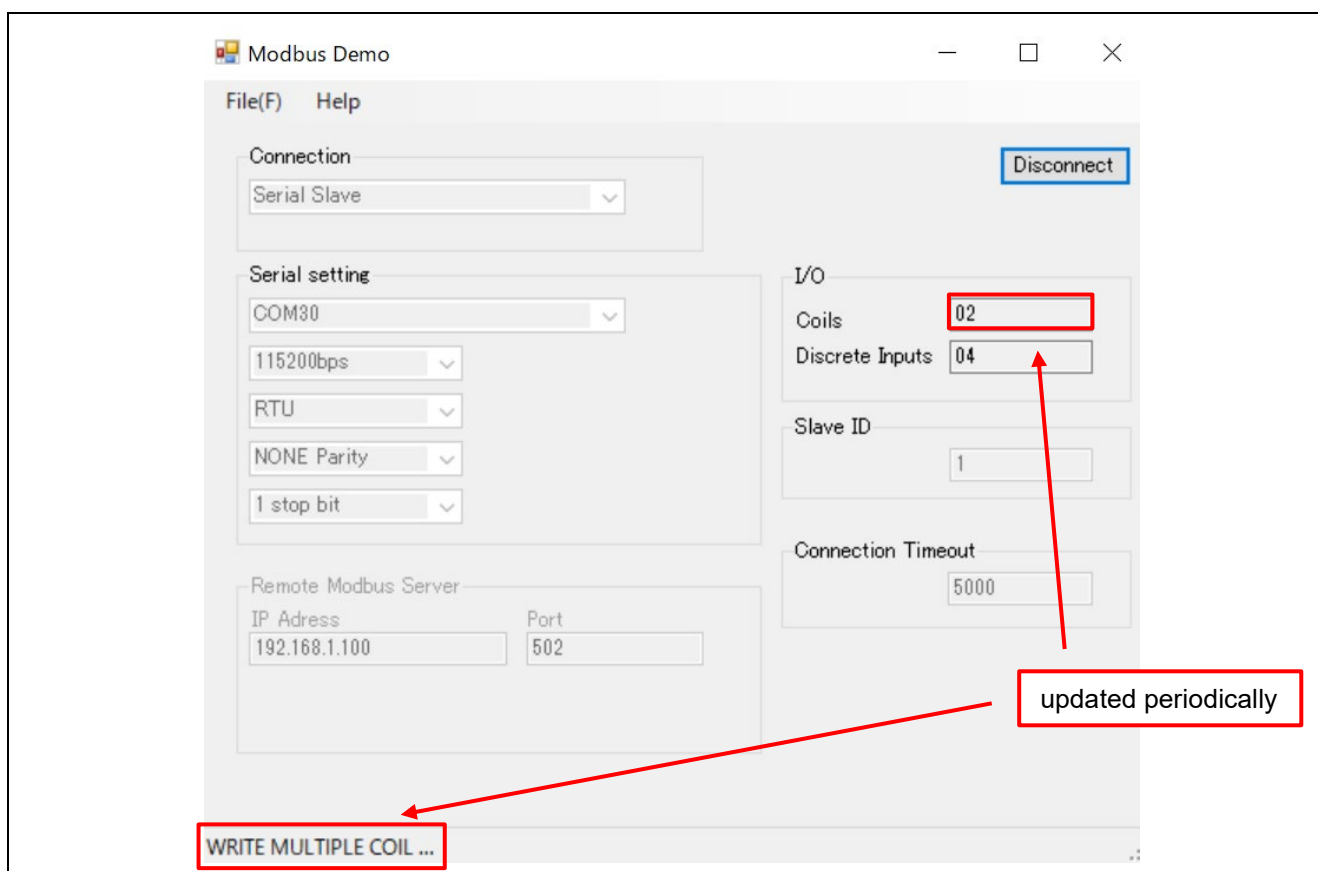
By communicating with PC through the Modbus RTU / ASCII protocol, LED blinking speed is controlled dynamically.

For this control, "Read_Discrete_Inputs" and "Write_Single_Coil" function codes are used. Specifically, the following sequence is executed.

PC application checks the state of the switch (SW1), by using Modbus "Read_Discrete_Inputs" function code. The [SW setting value] is the 8-bits of data calculated by the state of SW1.

According to the state of the switch, the states of the output ports, which are connected to LED, are updated periodically.

Note) The LED used depends on the CPU running the project. For example, LED4 blinks when CR52_1 is used, and LED8 blinks when CA55_2 is used.

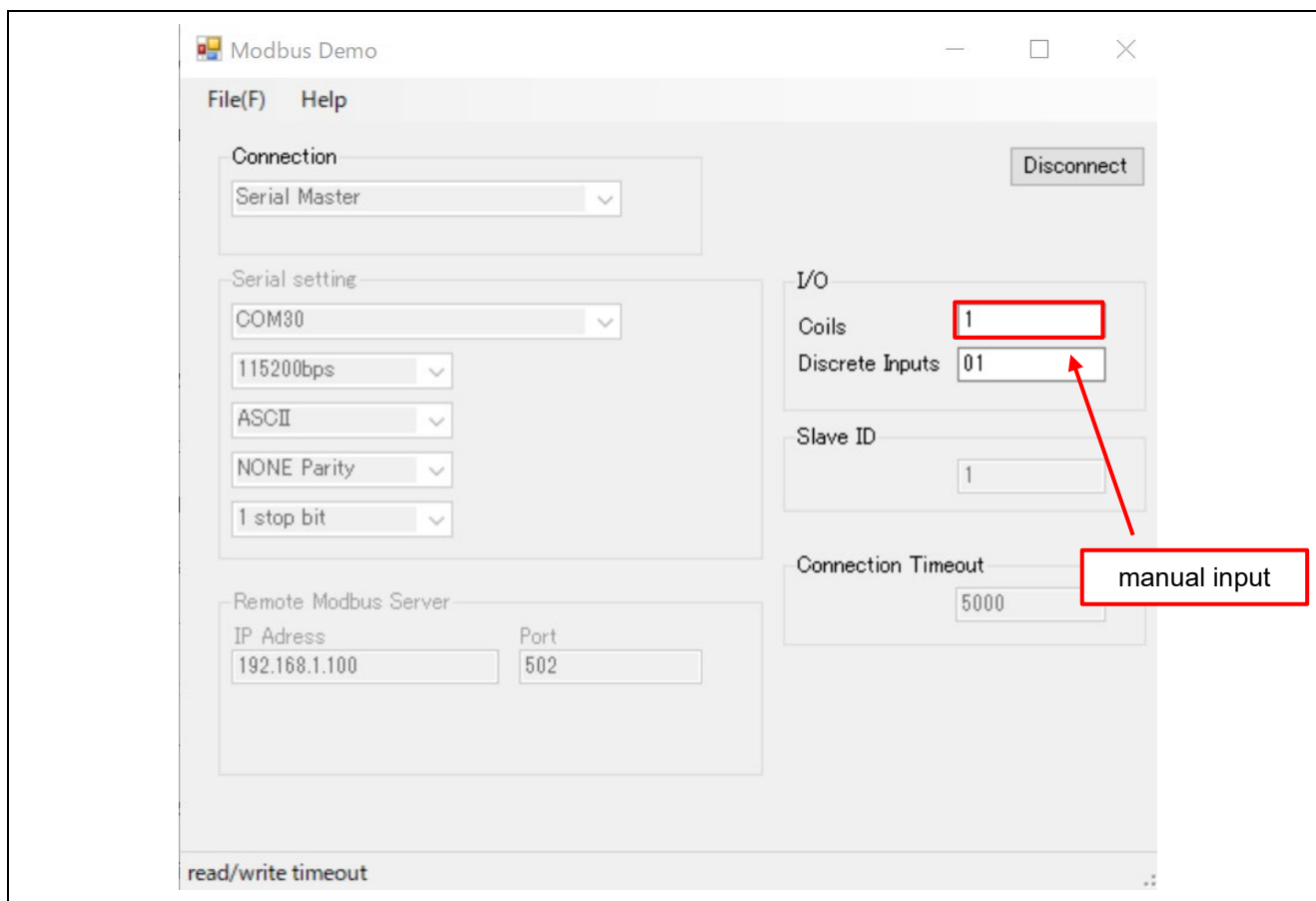


5.3.2 Client Application

Users can see the simple demonstration using this Modbus protocol stack in this sample project. By communicating with PC through the Modbus RTU / ASCII protocol, LED ON/OFF switching is controlled. For this control, "Read_Discrete_Inputs" and "Write_Single_Coil" function codes are used. Specifically, the following sequence is executed.

LED lights up depending on the manual input of the coil value of the demo application's I/O.

Note) The LED used depends on the CPU running the project. For example, LED4 blinks when CR52_1 is used, and LED8 blinks when CA55_2 is used.



6. Appendix

6.1 Appendix A. Setting the baud rate.

1. Open "RZN2H_Modbus_EVB_rev0410\Modbus_serial\common\renesas\modbus_user\modbus_init.c"
2. Change the following variables.

```
/* serial connection setting */  
st_init_info.u32_baud_rate = UART_BAUD_115200;  
/* Baud rate for serial port configuration, supported baud rate values are 9600 to 115200 bps */
```

The values that can be set are 115200, 76800, 38400, 31250, 19200 or 9600.

The timeout period is calculated based on the baud rate setting above.

6.2 Appendix B. Setting Server ID

1. When changing the Server ID, please change the following settings. (range : 1 to 247)
"RZN2H_Modbus_EVB_rev0410\Modbus_serial\common\renesas\modbus_user\modbus_init.c"
2. Build and debug.

```
#ifdef MODBUS_ASCII /* ASCII Slave mode */  
    MODBUS_ASCII_SLAVE_MODE,  
#else  
    /* RTU Slave mode */  
    MODBUS_RTU_SLAVE_MODE,  
#endif  
    1); /* Slave ID */  
#endif
```

7. Limitations

There is no limitation.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Dec 23, 2024	-	First Edition issued
2.11	Jun 20, 2025	-	- Added FSP2.2 compatibility method - Change the switch settings for the MP board
3.00	Nov 28, 2025	-	Supports RZ/N2 FSP3.0.0
4.00	Apr 10, 2026	-	Supports RZ FSP4.0.0
4.10	Jul 31, 2026	-	Supports RZ FSP4.1.0

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
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